

Advanced Lighting Management Unit

Check for Samples: LP3954

FEATURES

- Audio Synchronization for Color/RGB LEDs
- Command Based PWM Controlled RGB LED Drivers
- High Current Driver for Flash LED With Built-in Timing
- 4+2 or 6 Low Voltage Constant Current White LED Drivers With Orogrammable 8-Bit Adjustment (0...25mA/LED)
- High Efficiency Boost DC-DC Converter
- SPI / I²C Compatible Interface
- Possibility for External PWM Dimming Control
- Possibility for Clock Synchronization for RGB Timing
- Ambient Light and Temperature Sensing Possibility
- Small Package DSBGA, 3.0 x 3.0 x 0.6mm

APPLICATIONS

- Cellular Phones
- PDAs, MP3 players

DESCRIPTION

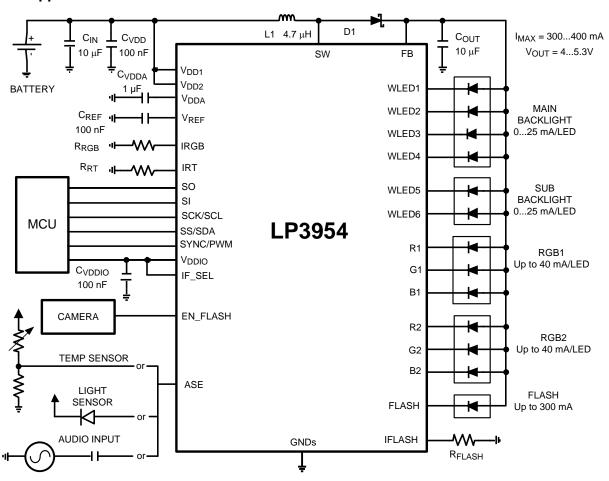
LP3954 is an advanced lighting management unit for handheld devices. It drives any phone lights including display backlights, RGB, keypad and camera flash LEDs. The boost DC-DC converter drives high current loads with high efficiency. White LED backlight drivers are high efficiency low voltage structures with excellent matching and automatic fade in/ fade out function. The new stand-alone command based RGB controller is feature rich and easy to configure. Built-in audio synchronization feature allows user to synchronize the color LEDs to audio input. Integrated high current driver can drive camera flash LED or motor/vibra. Internal ADC can be used for ambient light or temperature sensing. The flexible SPI/I²C interface allows easy control of LP3954. Small DSBGA package together with minimum number of external components is a best fit for handheld devices.

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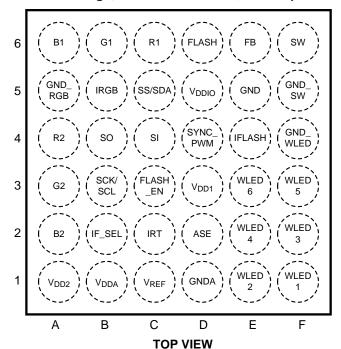
Typical Application





Connection Diagrams

DSBGA Package, 3.0 x 3.0 x 0.6mm, 0.5mm pitch Package Number YZR0036AAA or DSBGA Package, 3.0 x 3.0 x 0.65mm, 0.5mm pitch Package Number YPG0036AAA



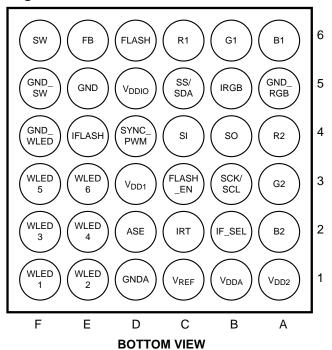




Table 1. Pin Descriptions

Pin No.	Name	Туре	Description		
6F	SW	Output	Boost Converter Power Switch		
6E	FB	Input	Boost Converter Feedback		
6D	FLASH	Output	High Current Flash Output		
6C	R1	Output	Red LED 1 Output		
6B	G1	Output	Green LED 1 Output		
6A	B1	Output	Blue LED 1 Output		
5F	GND_SW	Ground	Power Switch Ground		
5E	GND	Ground	Ground		
5D	VDDIO	Power	Supply Voltage for Input/output Buffers and Drivers		
5C	SS/SDA	Logic Input/Output	Slave Select (SPI), Serial Data In/Out (I ² C)		
5B	IRGB	Input	Bias Current Set Resistor for RGB Drivers		
5A	GND_RGB	Ground	Ground for RGB Currents		
4F	GND_WLED	Ground	Ground for WLED Currents		
4E	IFLASH	Input	High Current Flash Current Set Resistor		
4D	SYNC_PWM	Logic Input	External PWM Control for LEDs or External Clock for RGB Sync		
4C	SI	Logic Input	Serial Input (SPI), Address Select (I ² C)		
4B	SO	Logic Output	Serial Data Out (SPI)		
4A	R2	Output	Red LED 2 output		
3F	WLED5	Output	White LED 5 output		
3E	WLED6	Output	White LED 6 output		
3D	VDD1	Power	Supply voltage		
3C	EN_FLASH	Logic Input	Enable for High Current Flash		
3B	SCK/SCL	Logic Input	Clock (SPI/I ² C)		
3A	G2	Output	Green LED 2 Output		
2F	WLED3	Output	White LED 3 output		
2E	WLED4	Output	White LED 4 output		
2D	ASE	Input	Audio Synchronization Input		
2C	IRT	Input	Oscillator Frequency Resistor		
2B	IF_SEL	Logic Input	Interface (SPI or I ² C compatible) Selection (IF_SEL = 1 for SPI)		
2A	B2	Output	Blue LED 2 Output		
1F	WLED1	Output	White LED 1 Output		
1E	WLED2	Output	White LED 2 Output		
1D	GNDA	Ground	Ground for Analog Circuitry		
1C	VREF	Output	Reference Voltage		
1B	VDDA	Power	Internal LDO Output		
1A	VDD2	Power	Supply Voltage		





These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings (1) (2)(3)

Absolute maximum ratings	
V (SW, FB, R1-2, G1-2, B1-2, FLASH, WLED1-6) (4) (5)	-0.3V to +7.2V
$V_{DD1}, V_{DD2}, V_{DD_IO}, V_{DDA}$	-0.3V to +6.0V
Voltage on ASE, IRT, IFLASH, IRGB, VREF	-0.3V to V _{DD1} +0.3V with 6.0V max
Voltage on Logic Pins	-0.3V to V_{DD_IO} +0.3V with 6.0V max
V(all other pins): Voltage to GND	-0.3V to 6.0V
I (V _{REF})	10μΑ
I(R1, G1, B1, R2, G2, B2)	100mA
I(FLASH) ⁽⁶⁾	400mA
Continuous Power Dissipation ⁽⁷⁾	Internally Limited
Junction Temperature (T _{J-MAX})	150°C
Storage Temperature Range	-65°C to +150°C
Maximum Lead Temperature (Soldering) (8)	260°C
ESD Rating, Human Body Model (9)	2kV

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the component may occur. Operating Ratings are conditions under which operation of the device is ensured. Operating Ratings do not imply ensured performance limits. For ensured performance limits and associated test conditions, see the Electrical Characteristics tables.
- (2) All voltages are with respect to the potential at the GND pins.
- (3) If Military/Aerospace specified devices are required, please contact the TI Sales Office/Distributors for availability and specifications.
- (4) Battery/Charger voltage should be above 6V no more than 10% of the operational lifetime.
- (5) Voltage tolerance of LP3954 above 6.0V relies on fact that V_{DD1} and V_{DD2} (2.8V) are available (ON) at all conditions. If V_{DD1} and V_{DD2} are not available (ON) at all conditions, TI does not ensure any parameters or reliability for this device.
- (6) The total load current of the boost converter in worst-case conditions should be limited to 300mA (min. input and max. output voltage).
- (7) Internal thermal shutdown circuitry protects the device from permanent damage. Thermal shutdown engages at T_J=160°C (typ.) and disengages at T_J=140°C (typ.).
- (8) For detailed soldering specifications and information, please refer to Application Note AN1112: Micro SMD Wafer Level Chip Scale Package SNVA009 or Application Note AN1412: Micro SMDxt Wafer Level Chip Scale Package SNVA131.
- (9) The Human body model is a 100pF capacitor discharged through a 1.5kΩ resistor into each pin. The machine model is a 200pF capacitor discharged directly into each pin. MIL-STD-883 3015.7

Operating Ratings (1) (2)

- 1	
V (SW, FB, WLED1-6, R1-2, G1-2, B1-2, FLASH)	0 to 6.0V
V _{DD1,2} with external LDO	2.7 to 5.5V
V _{DD1,2} with internal LDO	3.0 to 5.5V
V_{DDA}	2.7 to 2.9V
V_{DD_IO}	1.65V to V _{DD1}
Voltage on ASE	0.1V to V _{DDA} –0.1V
Recommended Load Current	0mA to 300mA
Junction Temperature (T _J) Range	-30°C to +125°C
Ambient Temperature (T _A) Range ⁽³⁾	-30°C to +85°C

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the component may occur. Operating Ratings are conditions under which operation of the device is ensured. Operating Ratings do not imply ensured performance limits. For ensured performance limits and associated test conditions, see the Electrical Characteristics tables.
- (2) All voltages are with respect to the potential at the GND pins.
- (3) In applications where high power dissipation and/or poor package thermal resistance is present, the maximum ambient temperature may have to be derated. Maximum ambient temperature (T_{A-MAX}) is dependent on the maximum operating junction temperature (T_{J-MAX-OP} = 125°C), the maximum power dissipation of the device in the application (P_{D-MAX}), and the junction-to ambient thermal resistance of the part/package in the application (θ_{JA}), as given by the following equation: T_{A-MAX} = T_{J-MAX-OP} (θ_{JA} × P_{D-MAX}).

Thermal Properties

•	
Junction-to-Ambient Thermal Resistance(θ_{JA}), YZR0036AAA or YPG0036AAA Package ⁽¹⁾	60°C/W

 Junction-to-ambient thermal resistance is highly application and board-layout dependent. In applications where high maximum power dissipation exists, special care must be paid to thermal dissipation issues in board design.

Product Folder Links: LP3954



Electrical Characteristics (1) (2)

Limits in standard typeface are for $T_J = 25^\circ$ C. Limits in **boldface** type apply over the operating ambient temperature range (-30°C < T_A < +85°C). Unless otherwise noted, specifications apply to the LP3954 Block Diagram with: $V_{DD1} = V_{DD2} = 3.6V$, $V_{DDIO} = 2.8V$, $C_{VDD} = C_{VDDIO} = 100$ nF, $C_{OUT} = C_{IN} = 10$ µF, $C_{VDDA} = 1$ µF, $C_{REF} = 100$ nF, $L_1 = 4.7$ µH, $R_{FLASH} = 1.2$ k, $R_{RGB} = 5.6$ k and $R_{RT} = 82$ k $^{(3)}$.

Parameter		Test Conditions	Min	Тур	Max	Unit
I _{VDD} Standby supply current (V _{DD1} , V _{DD2})		NSTBY = L SCK, SS, SI		1	8	μA
	No-boost supply current (V _{DD1} , V _{DD2})	NSTBY = H, EN_BOOST = L SCK, SS, SI Audio sync and LEDs OFF			400	μΑ
	No-load supply current (V _{DD1} , V _{DD2})	NSTBY = H, EN_BOOST = H SCK, SS, SI Audio sync and LEDs OFF Autoload OFF			1	mA
	RGB drivers (V _{DD1} , V _{DD2})	CC mode at R1, G1, B1 and R2, G2, B2 set to 15mA		150		μΑ
		SW mode		150		
	WLED drivers (V _{DD1} , V _{DD2})	4+2 banks I _{OUT} /LED 25mA		500		μΑ
	Audio synchronization	Audio sync ON				
	(V_{DD1}, V_{DD2})	$V_{DD1,2} = 2.8V$		390		μA
		$V_{DD1,2} = 3.6V$		700		
	Flash (V _{DD1} , V _{DD2})	I(R _{FLASH})=1mA Peak current during flash		2		mA
I_{VDDIO}	V _{DDIO} Standby Supply current	NSTBY = L SCK, SS, SI = H			1	μΑ
	V _{DDIO} supply current	1MHz SCK frequency in SPI mode, C _L = 50pF at SO pin		20		μΑ
EXT_LDO	External LDO output current (V _{DD1} , V _{DD2} , V _{DDA})	7V tolerant application only I _{BOOST} = 300mA			6.5	mA
V_{DDA}	Output voltage of internal LDO	(4)	2.72	2.80	2.88	V
	for analog parts		-3		+3	%

⁽¹⁾ All voltages are with respect to the potential at the GND pins.

⁽²⁾ Min and Max limits are ensured by design, test, or statistical analysis. Typical numbers are not ensured, but do represent the most likely norm.

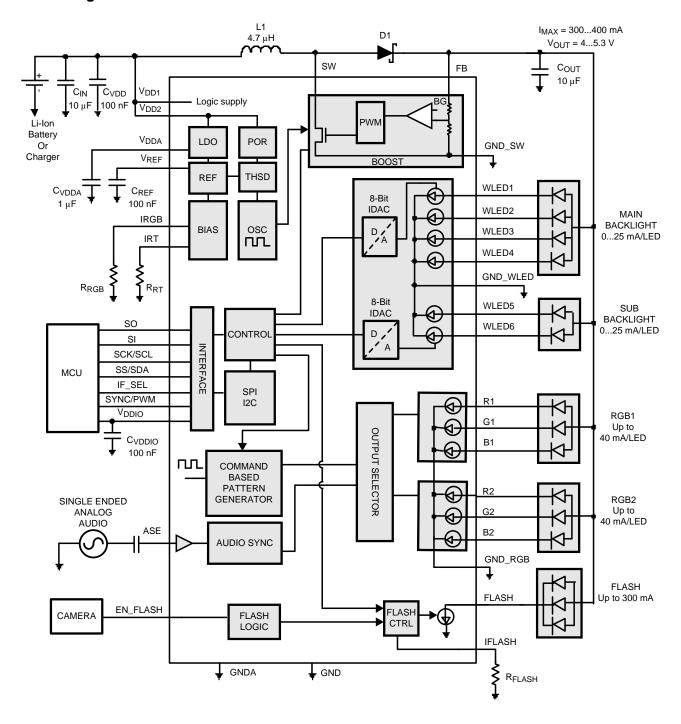
⁽³⁾ Low-ESR Surface-Mount Ceramic Capacitors (MLCCs) used in setting electrical characteristics.

⁽⁴⁾ V_{DDA} output is not recommended for external use.



DETAILED DESCRIPTION

Block Diagram





Modes of Operation

- RESET: In the RESET mode all the internal registers are reset to the default values and the chip goes to STANDBY mode after reset. NSTBY control bit is low after reset by default. Reset is entered always if Reset Register is written or internal Power On Reset is active. There is no dedicated Reset pin available. LP3954 can be reset by writing any data to Reset Register in address 60H. Power On Reset (POR) will activate during the chip startup or when the supply voltage VDD2 falls below 1.5V. Once VDD2 rises above 1.5V, POR will inactivate and the chip will continue to the STANDBY mode.
- **STANDBY:** The STANDBY mode is entered if the register bit NSTBY is LOW. This is the low power consumption mode, when all circuit functions are disabled. Registers can be written in this mode and the control bits are effective immediately after power up.
- **STARTUP:** When NSTBY bit is written high, the INTERNAL STARTUP SEQUENCE powers up all the needed internal blocks (Vref, Bias, Oscillator etc..). To ensure the correct oscillator initialization, a 10ms delay is generated by the internal state-machine. If the chip temperature rises too high, the Thermal Shutdown (THSD) disables the chip operation and STARTUP mode is entered until no thermal shutdown event is present.
- **BOOST STARTUP:** Soft start for boost output is generated in the BOOST STARTUP mode. The boost output is raised in PFM mode during the 10ms delay generated by the state-machine. The Boost startup is entered from Internal Startup Sequence if EN_BOOST is HIGH or from Normal mode when EN_BOOST is written HIGH. During the 10ms Boost Startup time all LED outputs are switched off to ensure smooth start-up.
- **NORMAL:** During NORMAL mode the user controls the chip using the Control Registers. The registers can be written in any sequence and any number of bits can be altered in a register in one write

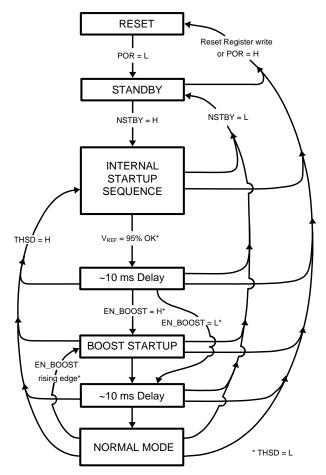


Figure 1. Modes of Operation

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Magnetic Boost DC/DC Converter

The LP3954 Boost DC/DC Converter generates a 4.0-5.3V voltage for the LEDs from single Li-Ion battery (3V...4.5V). The output voltage is controlled with an 8-bit register in 9 steps. The converter is a magnetic switching PWM mode DC/DC converter with a current limit. The converter has three options for switching frequency, 1MHz, 1.67MHz and 2MHz (default), when timing resistor RT is 82kohm. Timing resistor defines the internal oscillator frequency and thus directly affects boost frequency and all circuit's internally generated timing (RGB, Flash, WLED fading).

The LP3954 Boost Converter uses pulse-skipping elimination to stabilize the noise spectrum. Even with light load or no load a minimum length current pulse is fed to the inductor. An active load is used to remove the excess charge from the output capacitor at very light loads. At very light load and when input and output voltages are very close to each other, the pulse skipping is not completely eliminated. Output voltage should be at least 0.5V higher than input voltage to avoid pulse skipping. Reducing the switching frequency will also reduce the required voltage difference.

Active load can be disabled with the en_autoload bit. Disabling will increase the efficiency at light loads, but the downside is that pulse skipping will occur. The Boost Converter should be stopped when there is no load to minimise the current consumption.

The topology of the magnetic boost converter is called CPM control, current programmed mode, where the inductor current is measured and controlled with the feedback. The user can program the output voltage of the boost converter. The output voltage control changes the resistor divider in the feedback loop.

The following figure shows the boost topology with the protection circuitry. Four different protection schemes are implemented:

- 1. Over voltage protection, limits the maximum output voltage
 - Keeps the output below breakdown voltage.
 - Prevents boost operation if battery voltage is much higher than desired output.
- 2. Over current protection, limits the maximum inductor current
 - Voltage over switching NMOS is monitored; too high voltages turn the switch off.
- 3. Feedback break protection. Prevents uncontrolled operation if FB pin gets disconnected.
- 4. Duty cycle limiting, done with digital control.

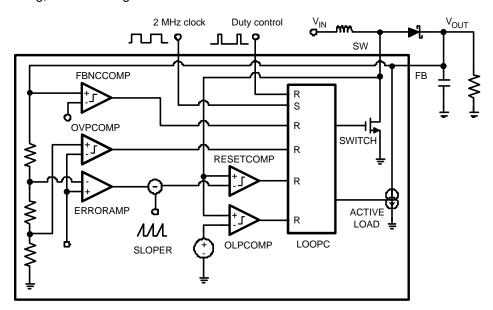


Figure 2. Boost Converter Topology



MAGNETIC BOOST DC/DC CONVERTER ELECTRICAL CHARACTERISTICS

	Parameter	Test Conditions	Test Conditions Min		Max	Unit
I _{LOAD}	Load Current	$3.0V \le V_{IN}$ $V_{OUT} = 5V$	0		300	A
		$3.0V \le V_{IN}$ $V_{OUT} = 4V$	0		400	- mA
V _{OUT}	Output Voltage Accuracy (FB Pin)	$3.0V \le V_{IN} \le V_{OUT} - 0.5$ $V_{OUT} = 5.0V$	-5		+5	%
	Output Voltage (FB Pin)	1 mA \leq I _{LOAD} \leq 300 mA V _{IN} > 5V + V _(SCHOTTKY)		V _{IN} -V _{(SCHOTT}		V
RDS _{ON}	Switch ON Resistance	$V_{DD1,2} = 2.8V$, $I_{SW} = 0.5A$		0.4	0.8	Ω
f _{PWF}	PWM Mode Switching Frequency	RT = $82 \text{ k}\Omega$ freq_sel[2:0] = $1XX$		2		MHz
	Frequency Accuracy	2.7 ≤ VDDA ≤ 2.9	-6	±3	+6	0/
		RT = 82 kΩ	-9		+9	%
t _{PULSE}	Switch Pulse Minimum Width	no load		25		ns
t _{STARTUP}	Startup Time	Boost startup from STANDBY		10		ms
I _{SW_MAX}	SW Pin Current Limit		700	800	900	A
			550		950	mA

BOOST STANDBY MODE

User can stop the Boost Converter operation by writing the Enables register bit EN_BOOST low. When EN_BOOST is written high, the converter starts for 10ms in PFM mode and then goes to PWM mode.

BOOST OUTPUT VOLTAGE CONTROL

User can control the boost output voltage by boost output 8-bit register.

Boost O	Boost Output Voltage (typical)	
Bin	Hex	
0000 0000	00	4.00
0000 0001	01	4.25
0000 0011	03	4.40
0000 0111	07	4.55
0000 1111	0F	4.70
0001 1111	1F	4.85
0011 1111	3F	5.00 Default
0111 1111	7F	5.15
1111 1111	FF	5.30

Product Folder Links: *LP*3954



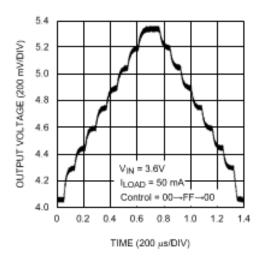


Figure 3. Boost Output Voltage Control

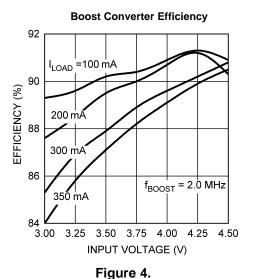
BOOST FREQUENCY CONTROL

freq_sel[2:0] ⁽¹⁾	frequency
1XX	2.00 MHz
01X	1.67 MHz
001	1.00 MHz

(1) Register 'boost freq' (address 0EH). Register default value after reset is 07H.

Boost Converter Typical Performance Characteristics

Vin = 3.6V, Vout = 5.0V if not otherwise stated



Boost Typical Waveforms at 100mA Load

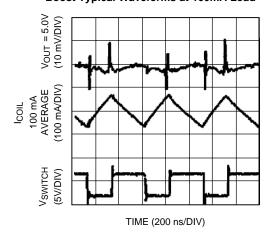


Figure 5.



Vin = 3.6V, Vout = 5.0V if not otherwise stated

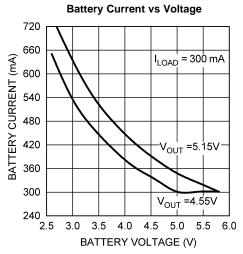
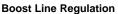


Figure 6.



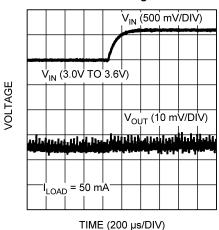


Figure 8.

Boost Load Transient, 50 mA-100 mA

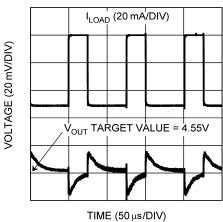


Figure 10.

Battery Current vs Voltage

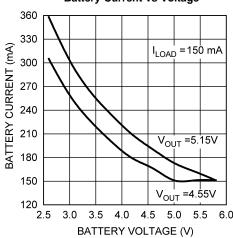


Figure 7.

Boost Startup with No Load

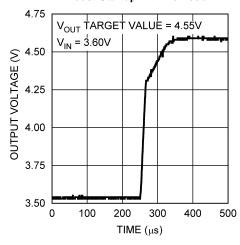


Figure 9.

Boost Switching Frequency

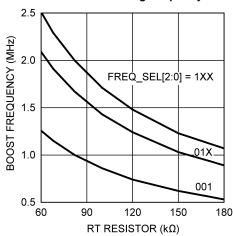
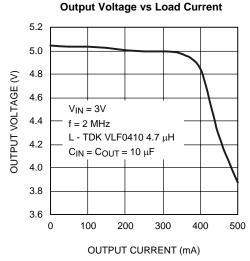


Figure 11.



Vin = 3.6V, Vout = 5.0V if not otherwise stated





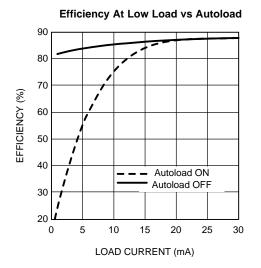


Figure 13.

Functionality of Color LED Outputs (R1, G1, B1; R2, G2, B2)

LP3954 has 2 sets of RGB/color LED outputs. Both sets have 3 outputs and the sets can be controlled in 4 different ways:

- 1. Command based pattern generator control (internal PWM)
- 2. Audio synchronization control
- 3. Direct ON/OFF control
- 4. External PWM control

By using **command based pattern generator** user can program any kind of color effect patterns. LED intensity, blinking cycles and slopes are independently controlled with 8 16-bit commands. Also real time commands are possible as well as loops and step by step control. If analog audio is available on system, the user can use **audio synchronization** for synchronizing LED blinking to the music. The different modes together with the various sub modes generate very colorful and interesting lighting effects. **Direct ON/OFF** control is mainly for switching on and off LEDs. **External PWM control** is for applications where external PWM signal is available and required to control the color LEDs. PWM signal can be connected to any color LED separately as shown later.

COLOR LED CONTROL MODE SELECTION

The RGB_SEL[1:0] bits in the Enables register (08H) control the output modes for RGB1 (R1, G1, B1) and RGB2 (R2, G2, B2) outputs. The following table shows the RGB_SEL functionality.

RGB_SEL[1:0]	Audio Sync Connected To	Command Based Pattern Generator Connected To
00	none	RGB1 & RGB2
01	RGB1	RGB2
10	RGB2	RGB1
11	RGB1 & RGB2	none

RGB Control register (00H) has control bits for direct on/off control of all color LEDs. Note that the LEDs have to be turned on in order to control them with audio synchronization or pattern generator.

The external PWM signal controls any LED depending on the control register setup. The controls are in the Ext. PWM Control register (address 07H) except the FLASH control in HC_Flash (10H) register as follows:

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(2)



Ext. PWM Control ⁽¹⁾				
wled1-4_pwm bit 7		PWM controls WLED 1-4		
wled5-6_pwm	bit 6	PWM controls WLED 5-6		
r1_pwm	bit 5	PWM controls R1 output		
g1_pwm bit 4		PWM controls G1 output		
b1_pwm bit 3		PWM controls B1 output		
r2_pwm bit 2		PWM controls R2 output		
g2_pwm	bit 1	PWM controls G2 output		
b2_pwm bit 0		PWM controls B2 output		
HC_Flash				
hc_pwm bit 5 PWM controls high current flas		PWM controls high current flash		

Note: If DISPL=1, wled1-4pwm controls WLED1-6
 Note: Maximum external PWM frequency is 1kHz. If during the external PWM control the internal PWM is on the result will be product of both functions.

CURRENT CONTROL OF COLOR LED OUTPUTS (R1, R2, G1, G2, B1, B2)

Both RGB output sets can be separately controlled as constant current sinks or as switches. This is done using $cc_rgb1/2$ bits in the RGB control register. In constant current mode one or both RGB output sets are controlled with constant current sinks (no external ballast resistors required). The maximum output current for both drivers is set by one external resistor R_{RGB} . User can decrease the maximum current for an individual LED driver by programming as shown later.

The maximum current for all RGB drivers is set with R_{RGB}. The equation for calculating the maximum current is

$$I_{MAX} = 100 \times 1.23 \text{V} / (R_{RGB} + 50\Omega)$$
 (1)

where

I_{MAX} - maximum RGB current in any RGB output in constant current mode

1.23V - reference voltage

100 - internal current mirror multiplier

R_{RGB}- resistor value in Ohms

 50Ω - internal resistor in the I_{RGB} input

For example if 22mA is required for maximum RGB current R_{RGB} equals to

$$R_{RGB} = 100 \times 1.23 \text{V} / I_{MAX} - 50\Omega = 123 \text{V} / 0.022 \text{A} - 50\Omega = 5.54 \text{k}\Omega$$

Each individual RGB output has a separate maximum current programming. The control bits are in registers **RGB1 max current** and **RGB2 max current** (12H and 13H) and programming is shown in table below. The default value after reset is 00.

IR1[1:0], IG1[1:0], IB1[1:0], IR2[1:0], IG2[1:0], IB2[1:0]	Maximum Current/Output
00	0.25 × I _{MAX}
01	0.50 × I _{MAX}
10	0.75 × I _{MAX}
11	1.00 × I _{MAX}

SWITCH MODE

The switch mode is used if there is a need to connect parallel LEDs to output or if the RGB output current needs to be increased.

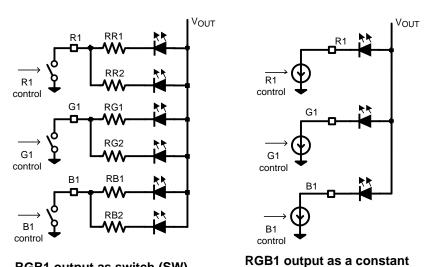
Please note that the switch mode requires an external ballast resistors at each output to limit the LED current.

The switch/current mode and on/off controls for RGB are in the RGB_ctrl register (00H) as follows:



Table 2. RGB_ctrl Register (00H)

		1	R1, G1 and B1 are switches → limit current with ballast resistor
CC_RGB1	bit7	0	R1, G1 and B1 are constant current sinks, current limited internally
CC DODA	h:+C	1	R2, G2 and B2 are switches → limit current with ballast resistor
CC_RGB2	bit6	0	R2, G2 and B2 are constant current sinks, current limited internally
*4 o	bit5	1	R1 is on
r1sw	CIIC	0	R1 is off
a1ow	bit4	1	G1 is on
g1sw	DIL4	0	G1 is off
b1sw	bit3	1	B1 is on
DISW	טווט	0	B1 is off
r2sw	bit2	1	R2 is on
125W	DILZ	0	R2 is off
g2sw	bit1	1	G2 is on
gzsw	DILI	0	G2 is off
b2sw	bit0	1	B2 is on
D25W	טווט	0	B2 is off



Command Based Pattern Generator for Color LEDs

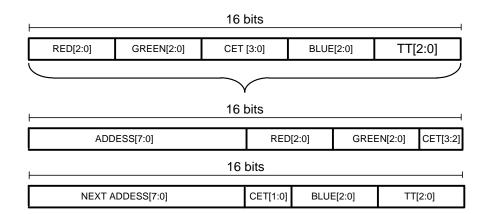
RGB1 output as switch (SW)

The LP3954 has a unique stand-alone command based pattern generator with 8 user controllable 16-bit wide commands. Since write registers are 8-bit long one command requires 2 write cycles. Each command has intensity level for each LED, command execution time (CET) and transition time (TT). The command structure is shown in following two figures.

current sink (CC)

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COMMAND REGISTER WITH 8 COMMANDS

COMMAND 1	ADDRESS 50H	R2	R1	R0	G2	G1	G0	CET3	CET2
	ADDRESS 51H	CET1	CET0	B2	B1	В0	TT2	TT1	TT0
COMMAND 2	ADDRESS 52H	R2	R1	R0	G2	G1	G0	CET3	CET2
	ADDRESS 53H	CET1	CET0	B2	B1	В0	TT2	TT1	TT0
COMMAND 3	ADDRESS 54H	R2	R1	R0	G2	G1	G0	CET3	CET2
	ADDRESS 55H	CET1	CET0	B2	B1	В0	TT2	TT1	TT0
COMMAND 4	ADDRESS 56H	R2	R1	R0	G2	G1	G0	CET3	CET2
	ADDRESS 57H	CET1	CET0	B2	B1	В0	TT2	TT1	TT0
COMMAND 5	ADDRESS 58H	R2	R1	R0	G2	G1	G0	CET3	CET2
	ADDRESS 59H	CET1	CET0	B2	B1	В0	TT2	TT1	TT0
COMMAND 6	ADDRESS 5AH	R2	R1	R0	G2	G1	G0	CET3	CET2
	ADDRESS 5BH	CET1	CET0	B2	B1	В0	TT2	TT1	TT0
COMMAND 7	ADDRESS 5CH	R2	R1	R0	G2	G1	G0	CET3	CET2
	ADDRESS 5DH	CET1	CET0	B2	B1	В0	TT2	TT1	TT0
COMMAND 8	ADDRESS 5EH	R2	R1	R0	G2	G1	G0	CET3	CET2
	ADDRESS 5FH	CET1	CET0	B2	B1	В0	TT2	TT1	TT0

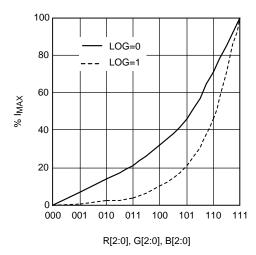
COLOR INTENSITY CONTROL

Each color, Red, Green and Blue, has 3-bit intensity levels. The level control is logarithmic. 2 logarithmic curves are available. The LOG bit in Pattern_gen_ctrl register (11H) defines the curve used. The values for both logarithmic curves are shown in following table.

R[2:0], G[2:0], B[2:0]	CURRENT [% × I _{MAX(COLOR)}]		
D[2.0]	LOG=0	LOG=1	
000	0	0	
001	7	1	
010	14	2	
011	21	4	
100	32	10	
101	46	21	
110	71	46	
111	100	100	

Product Folder Links: LP3954





COMMAND EXECUTION TIME (CET) AND TRANSITION TIME (TT)

The command execution CET time is the duration of one single command. Command execution times CET are defined as follows, when R_T =82k:

CET [3:0]	CET duration, ms
0000	197
0001	393
0010	590
0011	786
0100	983
0101	1180
0110	1376
0111	1573
1000	1769
1001	1966
1010	2163
1011	2359
1100	2556
1101	2753
1110	2949
1111	3146

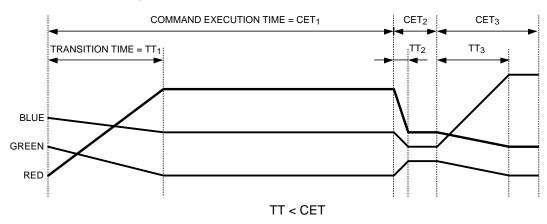
Transition time TT is duration of transition from the previous RGB value to programmed new value. Transition times TT are defined as follows:

TT [2:0]	Transition time, ms
000	0
001	55
010	110
011	221
100	442
101	885
110	1770
111	3539

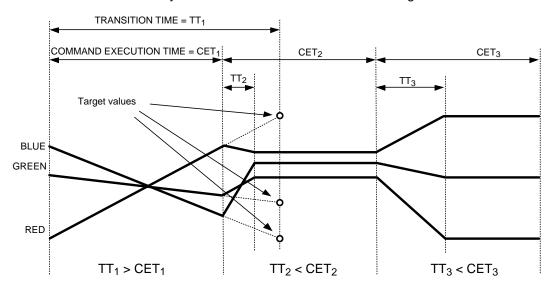
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The figure below shows an example of RGB CET and TT times.

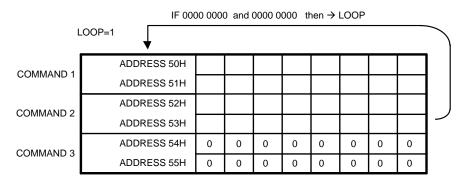


The command execution time also may be less than the transition time – the figure below illuminates this case.



LOOP CONTROL

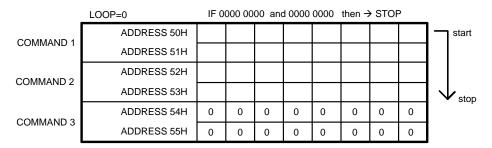
Pattern generator commands can be looped using the LOOP bit (D1) in Pattern gen ctrl register (11H). If LOOP=1 the program will be looped from the command 8 register or if there is 0000 0000 and 0000 0000 in one command register. The loop will start from command 1 and continue until stopped by writing rgb_start=0 or loop=0. The example of loop is shown in following figure:





SINGLE PROGRAM

If control bit LOOP=0 the program will start from Command 1 and run to either last command or to empty "0000 0000 / 0000 0000" command.



The LEDs maintain the brightness of the last command when the single program stops. Changes in command register will not be effective in this phase. The RGB_START bit has to be toggled off and on to make changes effective.

START BIT

Pattern_gen_ctrl register's RGB_START bit will enable command execution starting from Command 1.

Pattern gen ctrl register (11H)				
rgb_start	Bit 2	0 – Pattern generator disabled 1 – execution pattern starting from command 1		
loop	Bit 1	0 – pattern generator loop disabled (single pattern) 1 – pattern generator loop enabled (execute until stopped)		
log	Bit 0	0 – color intensity mode 0 1 – color intensity mode 1		

HARDWARE ON/OFF CONTROL AND DIMMING

PWM_LED input can be used as direct ON/OFF control or PWM dimming control for selected RGB outputs or the WLED groups. PWM_LED control can be enabled with the control bits in the **Ext. PWM Control** register.

Audio Synchronization

The color LEDs connected to RGB outputs can be synchronized to incoming audio with Audio Synchronization feature. Audio Sync has 2 modes. **Amplitude mode** synchronizes color LEDs based on input signal's peak amplitude. In the amplitude mode the user can select between 3 different amplitude mapping modes and 4 different speed configurations. The **frequency mode** synchronizes the color LEDs based on bass, middle and treble amplitudes (= low pass, band pass and high pass filters). User can select between 2 different frequency responses and 4 different speed configurations for best audio-visual user experience. Programmable gain and AGC function are also available for adjustment of input signal amplitude to light response. The Audio Sync functionality is described more closely below.

USING A DIGITAL PWM AUDIO SIGNAL AS AN AUDIO SYNCHRONIZATION SOURCE

If the input signal is a PWM signal, use a first or second order low pass filter to convert the digital PWM audio signal into an analog waveform. There are two parameters that need to be known to get the filter to work successfully: frequency of the PWM signal and the voltage level of the PWM signal. Suggested cut-off frequency (-3dB) should be around 2 kHz to 4 kHz and the stop-band attenuation at sampling frequency should be around 48dB or better. Use a resistor divider to reduce the digital signal amplitude to meet the specification of the analog audio input. Because a low-order low-pass filter attenuates the high-frequency components from audio signal, MODE_CONTROL=[01] selection is recommended when frequency synchronization mode is enabled. Application example 5 shows an example of a second order RC-filter for 29 kHz PWM signal with 3.3V amplitude. Active filters, such as a Sallen-Key filter, may also be applied. An active filter gives better stop-band attenuation and cut-off frequency can be higher than for a RC-filter.

Product Folder Links: LP3954

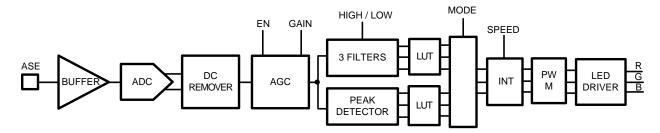


To make sure that the filter rolls off sufficiently quickly, connect your filter circuit to the audio input(s), turn on the audio synchronization feature, set manual gain to maximum, apply the PWM signal to the filter input and keep an eye on LEDs. If they are blinking without an audio signal (modulation), a sharper roll-off after the cut-off frequency, more stop-band attenuation, or smaller amplitude of the PWM signal is required.

AUDIO SYNCHRONIZATION SIGNAL PATH

LP3954 audio synchronization is mainly done digitally and it consists of the following signal path blocks:

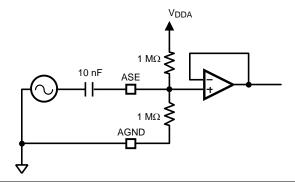
- Input Buffers
- AD Converter
- DC Remover
- Automatic Gain Control (AGC)
- Programmable Gain
- · 3 Band Digital Filter
- Peak Detector
- Look-up Tables (LUT)
- Mode Selector
- Integrators
- PWM Generator
- Output Drivers



The digitized input signal has DC component that is removed by digital **DC REMOVER** (-3dB at 400Hz). Since the light response of input audio signal is very much amplitude dependent the AGC adjusts the input signal to suitable range automatically. User can disable **AGC** and the gain can be set manually with **PROGRAMMABLE GAIN**. LP3954 has 2 audio synchronization modes: amplitude and frequency. For amplitude based synchronization the **PEAK DETECTION** method is used. For frequency based synchronization **3 BAND FILTER** separates high pass, low pass and band bass signals. For both modes the predefined LUT is used to optimize the audio visual effect. **MODE SELECTOR** selects the synchronization mode. Different response times to music beat can be selected using **INTEGRATOR** speed variables. Finally **PWM GENERATOR** sets the driver FET duty cycles.

INPUT SIGNAL TYPE AND BUFFERING

LP3954 supports single ended audio input as shown in the figure below. The electric parameters of the buffer are described in the Audio Synch table. The buffer is rail-to-rail input operational amplifier connected as a voltage follower. DC level of the input signal is set by a simple resistor divider





AUDIO SYNC ELECTRICAL PARAMETERS

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
Z _{IN}	Input Impedance of ASE		250	500		kOhm
A _{IN}	Audio Input Level Range (peak-to-peak)	Gain = 21dB	0.1			V
		Gain = 0 dB			V _{DDA} - 0.1	
f _{3dB}	Crossover Frequencies (-3 dB)					
	Narrow Frequency Response	Low Pass		0.5		
		Band Pass		1.0 and 1.5		
		High Pass		2.0		kHz
	Wide Frequency Response	Low Pass		1.0		
		Band Pass		2.0 and 3.0		
		High Pass		4.0		

CONTROL OF AUDIO SYNCHRONIZATION

The following table describes the controls required for audio synchronization.

		Audio_sync_	CTRL1 (2AH)			
		Input signal gain contro	ol. Range 021 dB, ste	p 3 dB:		
CAIN SELIZAD	Bits 7-5	[000] = 0 dB (default)	[011] = 9 dB	[110] = 18 dB		
GAIN_SEL[2:0]	DIIS 7-5	[001] = 3 dB	[100] = 12 dB	[111] = 21 dB		
		[010] = 6 dB	[101] = 15 dB			
SYNC_MODE Bit 4 Synchronization mode selector. SYNCMODE = 0 → Amplitude Mode (default) SYNCMODE = 1 → Frequency Mode						
EN_AGC	Bit 3	Automatic Gain Control enable 1 = enabled 0 = disabled (Gain Select enabled) (default)				
EN_SYNC	Bit 2	Audio synchronization enable 1 = Enabled Note: If AGC is enabled, AGC gain starts from current GAIN_SEL gain value. 0 = Disabled (default)				
INPUT_SEL[1:0]	Bits 1-0	[00] = Single ended input signal, ASE. [01] = Temperature measurement [10] = Ambient light measurement [11] = No input (default)				
		Audio_sync_	CTRL2 (2BH)			
EN_AVG	Bit 4		not applicable in audio s not applicable in audio s			
MODE_CTRL[1:0]	Bits 3-2	See below: Mode cont	rol			
SPEED_CTRL[1:0]	Bits 1-0	[00] = FASTEST (defa [01] = FAST [10] = MEDIUM [11] = SLOW	amplitude mode f _{MAX} =3.			

MODE CONTROL IN FREQUENCY MODE

Mode control has two setups based on audio synchronization mode select: the frequency mode and the amplitude mode. During the **frequency mode** user can select two filter options by MODE_CTRL as shown below. User can select the filters based on the music type and light effect requirements. In the first mode the frequency range extends to 8 kHz in the secont to 4 kHz.

The lowpass filter is used for the red, the bandpass filter for the blue and the hipass filter for the green LED.

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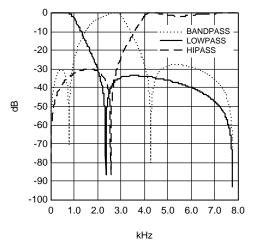


Figure 14. Higher frequency mode MODE_CTRL = 00 and SYNC_MODE = 1

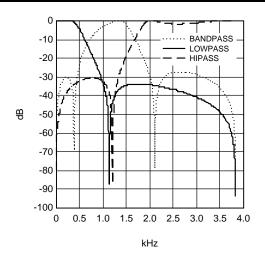


Figure 15. Lower frequency mode MODE_CTRL = 01 and SYNC_MODE = 1

MODE CONTROL IN AMPLITUDE MODE

During the **amplitude synchronization mode** user can select between three different amplitude mappings by using MODE_CTRL select. These three mapping option gives different light response. The modes are shown in the tables below.

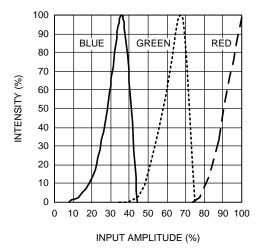


Figure 16. Non-overlapping mode MODE CTRL[1:0] = [01]

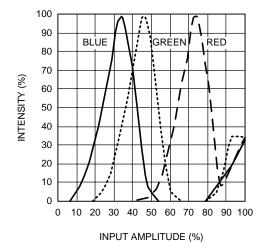
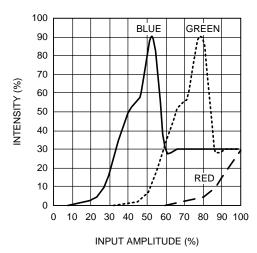


Figure 17. Partly overlapping mode MODE_CTRL[1:0] = [00]





5.00 3.00 2.50 2.00 PEAK INPUT SIGNAL VPP (V) 1.50 1.00 0.50 0.15 0.10 0.05 0 3 6 12 18 21 GAIN (dB)

Figure 18. Overlapping mode MODE_CTRL[1:0] = [10]

Figure 19. Peak Input Signal Level Range vs Gain Setting

RGB OUTPUT SYNCHRONIZATION TO EXTERNAL CLOCK

The RGB pattern generator and high current flash driver timing can be synchronized to external clock with following configuration.

- 1. Set PWM_SYNC bit in Enables register to 1
- 2. Feed PWM_SYNC pin with 5 MHz clock

By this the internal 5 MHz clock is disabled from pattern generator and flash timing circuitry.

The external clock signal frequency will fully determine the timings related to RGB and Flash.

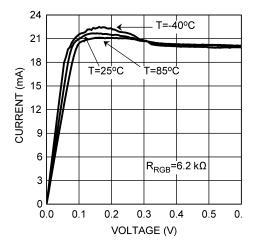
Note: The boost converter will use internal 5 MHz clock even if the external clock is available.

RGB Driver Typical Performance Characteristics

RGB DRIVER ELECTRICAL CHARACTERISTICS (R1, G1, B1, R2, G2, B2 OUTPUTS)

	Parameter	Test Conditions	Min	Тур	Max	Unit
I _{LEAKAGE}	R1, G1, B1, R2, G2, B2 pin leakage current			0.1	1	μА
I _{MAX(RGB)}	Maximum recommended sink	CC mode			40	mA
,	current ⁽¹⁾	SW mode			50	mA
	Accuracy at 37mA	R _{RGB} =3.3 kΩ ±1%, CC mode		±5		%
	Current mirror ratio	CC mode		1:100		
	RGB1 and RGB2 current mismatch	I _{RGB} =37mA, CC mode		±5		%
R _{SW}	Switch resistance	SW mode		2.5	4	Ω
f_{RGB}	RGB switching frequency	Accuracy proportional to internal clock freq.	18.2	20	21.8	kHz
		If external SYNC 5MHz is in use		20		kHz

 Note: RGB current should be limited as follows: constant current mode – limit by external R_{RGB} resistor; switch mode – limit by external ballast resistors



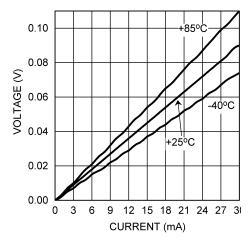


Figure 20. Output Current vs Pin Voltage (Current Sink Mode)

Figure 21. Pin Voltage vs Output Current (Switch Mode)

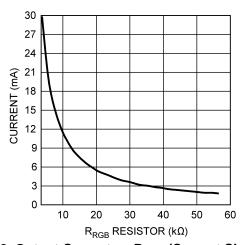


Figure 22. Output Current vs R_{RGB} (Current Sink Mode)

Single High Current Driver

LP3954 has internal constant current driver that is capable for driving high current mainly targeted for FLASH LED in camera phone applications.

MAXIMUM CURRENT SETUP FOR FLASH

The user sets the maximum current of FLASH with R_{FLASH} resistor based on following equation:

$$I_{MAX} = 300 \times 1.23 \text{V} / (R_{FLASH} + 50\Omega),$$
 (3)

where

Imax = maximum flash current in Amps (ie. 0.3A)

1.23V = reference voltage

300 = internal current mirror multiplier

 R_{FLASH} = Resistor value in Ohms

 50Ω = Internal resistor in the I_{FLASH} input

For example if 300mA is required for maximum flash current R_{FLASH} equals to

$$R_{FLASH} = 300 \times 1.23 \text{V} / I_{MAX} - 50\Omega = 369 \text{V} / 0.3 \text{A} - 50\Omega = 1.18 \text{k}\Omega$$

(4)



CURRENT CONTROL FOR FLASH

To minimize the internal current consumption, the flash function has an enable bit EN_HCFLASH in the HC_Flash register.

EN_HCFLASH	
0	FLASH disabled, no extra current consumption through R _{FLASH}
1	FLASH enabled, IFLASH set by HC_SW[1:0] (see below)

HC[1:0] bits in the HC_Flash register control the FLASH current as show in following table.

HC[1:0]	I(FLASH)
00	0.25 × I _{MAX(FLASH)}
01	$0.50 \times I_{MAX(FLASH)}$
10	$0.75 \times I_{MAX(FLASH)}$
11	1.00 × I _{MAX(FLASH)}

Figure 23 shows the internal structure for the FLASH driver.

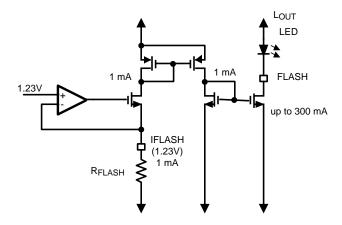


Figure 23. Internal Structure of Flash Driver

FLASH TIMING

Flash output is turned on in lower current **View finder** mode when the EN_HCFLASH bit is written high. The actual Flash at maximum current starts when the EN_FLASH i/o-pin goes high. The Flash length can be selected from 3 pre-defined values or EN_FLASH pin pulse length can determine the length. The pulse length is controlled by the FT_T[1:0] bits as show in the table below.

FL_T[1:0]	Flash Duration Typ	Current During View Finder/Focusing	Current During FLASH
00	200ms	Set by HC[1:0]	$HC[11] = I_{MAX(FLASH)}$
01	400ms	Set by HC[1:0]	$HC[11] = I_{MAX(FLASH)}$
10	600ms	Set by HC[1:0]	$HC[11] = I_{MAX(FLASH)}$
11	EN_FLASH on duration	Set by HC[1:0]	$HC[11] = I_{MAX(FLASH)}$

Product Folder Links: LP3954

Figure 24 shows the functionality of the built-in flash.

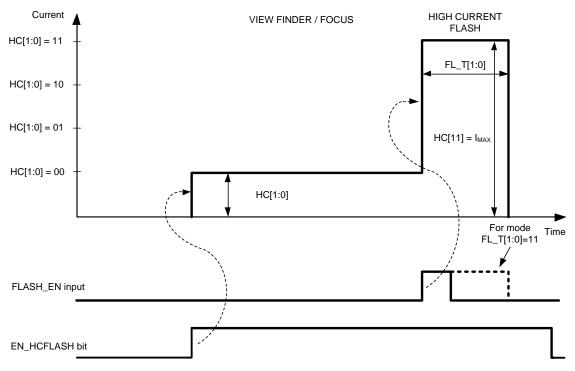


Figure 24. Built-In Flash

HIGH CURRENT DRIVER ELECTRICAL CHARACTERISTICS

	Parameter	Test Conditions	Min	Тур	Max	Unit
I _{LEAKAGE}	FLASH pin leakage current			0.1	2	μA
I _{MAX(FLASH)}	Maximum Sink Current				400	mA
	Accuracy at 300 mA	R _{FLASH} =1.18 kΩ ±1%		±5	±10	%
	Current mirror ratio			1:300		

Backlight Drivers

LP3954 has 2 independent backlight drivers. Both drivers are regulated constant current sinks. LED current for both LED banks (WLED1...4 and WLED5...6) are controlled by 8-bit current mode DACs with 0.1 mA step.

WLED1...4 and WLED5...6 can be also controlled with one DAC for better matching allowing the use of larger displays having up to 6 white LEDs in parallel.

Display configuration is controlled with DISPL bit as shown below.

DISPL	Configuration	Matching	
0	Main display up to 4 LEDs Good btw WLED14	Good btw WLED14	
U	Sub display up to 2 LEDs	Good btw WLED56	
1	Large display up to 6 LEDs	Good btw WLED 16	

Display backlight enables					
EN WA A	1	WLED1-4 enabled			
EN_W1-4	0	WLED1-4 disabled			
EN_W5-6 1 WLED5-6 ena		WLED5-6 enabled			
	0	WLED5-6 disabled			



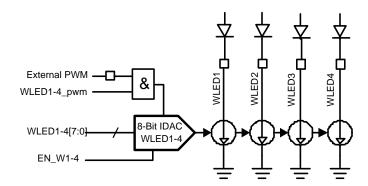


Figure 25. Main Display up to 4 LEDs (WLED1...4)

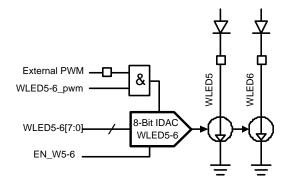


Figure 26. Sub Display Driver up to 2 LEDs (WLED5...6)

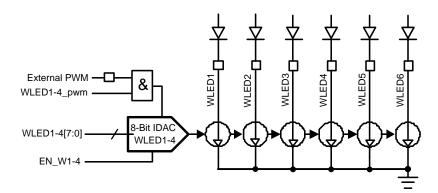


Figure 27. Main Display up to 6 LEDs (WLED1...6) (DISPL=1)

BACKLIGHT DRIVER ELECTRICAL CHARACTERISTICS

	Parameter	Test Conditions	Min	Typical	Max	Unit
I _{MAX}	Maximum Sink Current		21.3	25.5	29.4	mA
I _{Leakage}	Leakage Current	V _{FB} =5V		0.03	1	μΑ
I _{WLED1}	WLED1 Current tolerance	I _{WLED1} set to 12.8mA (80H)	10.52	12.8	14.78	mA
			-18		+16	%
I _{Match1-4}	Sink Current Matching	I _{SINK} =13mA, Between WLED14		0.2		%
I _{Match5-6}	Sink Current Matching	I _{SINK} =13mA, Between WLED56		0.2		%
I _{Match1-6}	Sink Current Matching	I _{SINK} =13mA, Between WLED16		0.3		%

Product Folder Links: LP3954



ADJUSTMENT

WLED1-4[7:0] WLED5-6[7:0]	Driver Current, mA (typical)
0000 0000	0
0000 0001	0.1
0000 0010	0.2
0000 0011	0.3
1111 1101	25.3
1111 1110	25.4
1111 1111	25.5

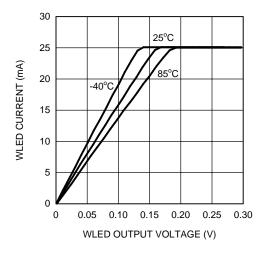


Figure 28. WLED Output Current vs. Voltage

FADE IN / FADE OUT

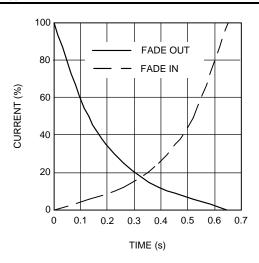
LP3954 has an automatic fade in and out for main and sub backlight. The fade function is enabled with EN_FADE bit. The slope of the fade curve is set by the SLOPE bit. Fade control for main and sub display is set by FADE_SEL bit.

EN FADE	0	Automatic fade disabled
EN_FADE	0 Automatic fade disabled 1 Automatic fade enabled 0 Fade execution time 1.3s 1 Fade execution time 0.65s 0 Fade controls WLED1-4	
SLODE	0	Fade execution time 1.3s
SLOPE	1	Fade execution time 0.65s
FADE CEL	0	Fade controls WLED1-4
FADE_SEL	1	Fade controls WLED5-6

Recommended fading sequence:

- 1. ASSUMPTION: Current WLED value in register
- 2. Set SLOPE
- 3. Set FADE_SEL
- 4. Set EN_FADE = 1
- 5. Set target WLED value
- 6. Fading will be done either within 0.5s or 1s based on Slope selection





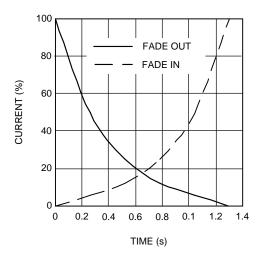


Figure 29. WLED Dimming, SLOPE=0

Figure 30. WLED Dimming, SLOPE=1

Ambient Light and Temperature Measurement with LP3954

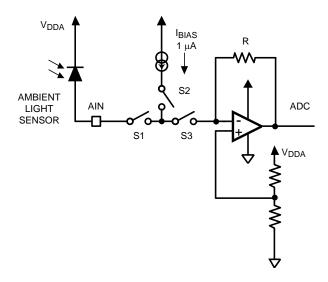
The Analog-to-Digital converter (ADC) in the Audio Syncronization block can be also used for ambient light measurement or temperature measurement.

The selection between these modes is controlled with input selector bits INPUT_SEL[1:0] as follows

INPUT_SEL[1:0]	Mode
00	Audio synchronization
01	Temperature measurement (voltage input)
10	Ambient light measurement (current input)
11	No input

AMBIENT LIGHT MEASUREMENT

The ambient light measurement requires only one external component: Ambient light sensor (photo transistor or diode). The ADC reads the current level at ASE pin and converts the result in digital word. User can read the ADC output from the ADC output register. The known ambient light condition allows user to set the backlight current to optimal level thus saving power especially in low light and bright sunlight condition.



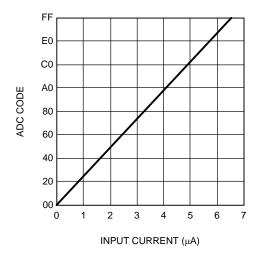


Figure 31. ADC Code vs Input Current in Light Measurement Mode

TEMPERATURE MEASUREMENT

The temperature measurement requires two external components: resistor and thermistor (resistor that has known temperature vs resistance curve). The ADC reads the voltage level at ASE pin and converts the result in digital word. User can read the ADC output from register. The known temperature allows for example to monitor the temperature inside the display module and decrease the current level of the LEDs if temperature raises too high. This function may increase lifetime of LEDs in some applications.

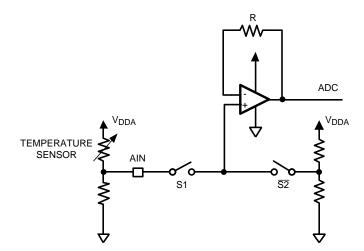
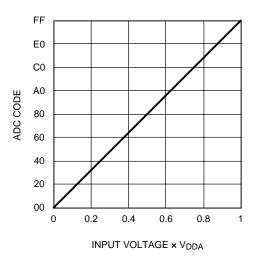


Figure 32. Temperature Sensor Connection Example





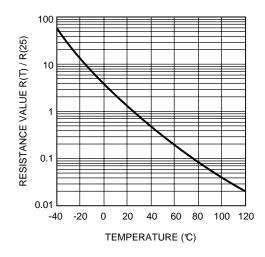


Figure 33. ADC Code vs Input Voltage in Temperature Measurement Mode

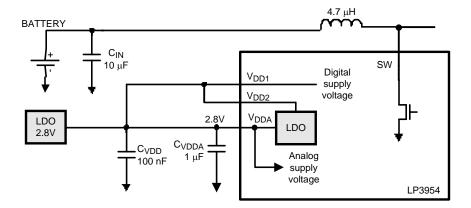
Figure 34. Example Curve for Thermistor

EXAMPLE TEMP SENSOR READING AT DIFFERENT TEMPERATURES (R(25°C)=1MΩ)

T°C	R(MΩ)	Rt(MΩ)	V(ASE)
-40	1	60	2.7540984
0	1	4	2.24
25	1	1	1.4
60	1	0.2	0.466667
100	1	0.04	0.1076923

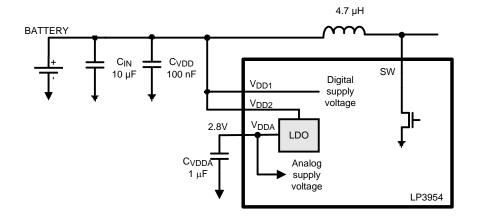
7V Shielding

To shield LP3954 from high input voltages 6...7.2V the use of external 2.8V LDO is required. This 2.8V voltage protects internally the device against high voltage condition. The recommended connection is as shown in the picture below. Internally both logic and analog circuitry works at 2.8V supply voltage. Both supply voltage pins should have separate filtering capacitors.



In cases where high voltage is not an issue the connection is as shown below.





Logic Interface Characteristics

 $(1.65V \le V_{DDIO} \le V_{DD1,2}V)$ (Unless otherwise noted)

	Parameter	Test Conditions	Min	Тур	Max	Unit
LOGIC	INPUTS SS, SI, SCK/SCL, SYNC/P	WM, IF_SEL, EN_FLASH	•			
V _{IL}	Input Low Level				0.2 × V _{DDIO}	V
V_{IH}	Input High Level		0.8 × V _{DDIO}			V
I	Logic Input Current		-1.0		1.0	μA
		I ² C Mode			400	kHz
f_{SCL}	Clock Frequency	SPI Mode, V _{DDIO} > 1.8V			13	MHz
		SPI Mode, 1.65V ≤ V _{DDIO} < 1.8V			5	MHz
LOGIC	OUTPUT SO					
\/	Output Louis Louis	$I_{SO} = 3 \text{ mA}$ $V_{DDIO} > 1.8 \text{V}$		0.3	0.5	V
V _{OL}	Output Low Level	$I_{SO} = 2 \text{ mA}$ 1.65V $\leq V_{DDIO} < 1.8V$		0.3	0.5	V
\/	Output High Lovel	$I_{SO} = -3 \text{ mA}$ $V_{DDIO} > 1.8 \text{V}$	V _{DDIO} – 0.5	V _{DDIO} - 0.3		V
V _{OH}	Output High Level	$I_{SO} = -2 \text{ mA}$ 1.65V $\leq V_{DDIO} < 1.8V$	V _{DDIO} - 0.5	V _{DDIO} - 0.3		
I _L	Output Leakage Current	V _{SO} = 2.8V			1.0	μA
LOGIC	OUTPUT SDA					
V _{OL}	Output Low Level	I _{SDA} = 3 mA		0.3	0.5	V

Control Interface

The LP3954 supports two different interface modes:

- SPI interface (4 wire, serial)
- I²C compatible interface (2 wire, serial)

User can define the serial interface by IF_SEL pin. IF_SEL=0 selects the I²C mode.



SPI INTERFACE

LP3954 is compatible with SPI serial bus specification and it operates as a slave. The transmission consists of 16-bit Write and Read Cycles. One cycle consists of 7 Address bits, 1 Read/Write (RW) bit and 8 Data bits. RW bit high state defines a Write Cycle and low defines a Read Cycle. SO output is normally in high-impedance state and it is active only when Data is sent out during a Read Cycle. A pull-up resistor may be needed in SO line if a floating logic signal can cause unintended current consumption in the input circuits where SO is connected. The Address and Data are transmitted MSB first. The Slave Select signal SS must be low during the Cycle transmission. SS resets the interface when high and it has to be taken high between successive Cycles. Data is clocked in on the rising edge of the SCK clock signal, while data is clocked out on the falling edge of SCK.

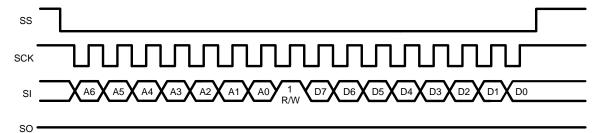


Figure 35. SPI Write Cycle

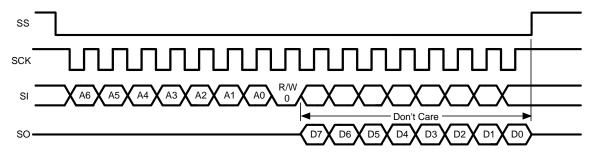


Figure 36. SPI Read Cycle

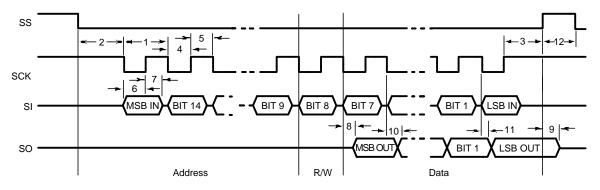


Figure 37. SPI Timing Diagram

SPI Timing Parameters

 $V_{DD} = V_{DD \ IO} = 2.775V$

Symbol	Davamatav	Limit ⁽¹⁾		l lmit
Symbol	Parameter	Min Max 70	Max	Unit
1	Cycle Time	70		ns
2	Enable Lead Time	35		ns

Note: Data ensured by design.



Symbol	Parameter	Limi	Limit ⁽¹⁾		
Symbol	Parameter	Min	Max	Unit	
3	Enable Lag Time	35		ns	
4	Clock Low Time	35		ns	
5	Clock High Time	35		ns	
6	Data Setup Time	20		ns	
7	Data Hold Time	0		ns	
8	Data Access Time		20	ns	
9	Disable Time		10	ns	
10	Data Valid		20	ns	
11	Data Hold Time	0		ns	

I²C COMPATIBLE INTERFACE

PC Signals

In I^2C mode the LP3954 pin SCK is used for the I^2C clock SCL and the pin SS is used for the I^2C data signal SDA. Both these signals need a pull-up resistor according to I^2C specification. SI pin is the address select pin. I^2C address for LP3954 is 54h when SI = 0 and 55h when SI = 1. Unused pin SO can be left unconnected.

PC Data Validity

The data on SDA line must be stable during the HIGH period of the clock signal (SCL). In other words, state of the data line can only be changed when CLK is LOW.

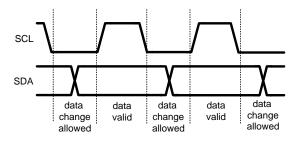
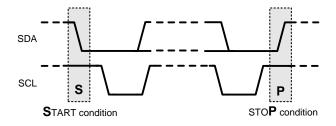


Figure 38. I²C Signals: Data Validity

PC Start and Stop Conditions

START and STOP bits classify the beginning and the end of the I²C session. START condition is defined as SDA signal transitioning from HIGH to LOW while SCL line is HIGH. STOP condition is defined as the SDA transitioning from LOW to HIGH while SCL is HIGH. The I²C master always generates START and STOP bits. The I²C bus is considered to be busy after START condition and free after STOP condition. During data transmission, I²C master can generate repeated START conditions. First START and repeated START conditions are equivalent, function-wise.





Transferring Data

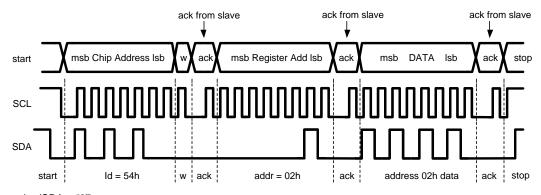
Every byte put on the SDA line must be eight bits long, with the most significant bit (MSB) being transferred first. Each byte of data has to be followed by an acknowledge bit. The acknowledge related clock pulse is generated by the master. The transmitter releases the SDA line (HIGH) during the acknowledge clock pulse. The receiver must pull down the SDA line during the 9th clock pulse, signifying an acknowledge. A receiver which has been addressed must generate an acknowledge after each byte has been received.

After the START condition, the I²C master sends a chip address. This address is seven bits long followed by an eighth bit which is a data direction bit (R/W). The LP3954 address is 54h or 55H as selected with SI pin. For the eighth bit, a "0" indicates a WRITE and a "1" indicates a READ. The second byte selects the register to which the data will be written. The third byte contains data to write to the selected register.



Figure 39. I²C Chip Address

Register changes take an effect at the SCL rising edge during the last ACK from slave.



w = write (SDA = "0")

r = read (SDA = "1")

ack = acknowledge (SDA pulled down by either master or slave)

rs = repeated start

id = 7-bit chip address, 54h (SI=0) or 55h (SI=1) for LP3954.

Figure 40. I²C Write Cycle

When a READ function is to be accomplished, a WRITE function must precede the READ function, as shown in the Read Cycle waveform.

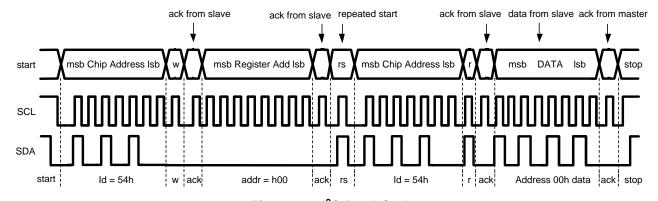


Figure 41. I²C Read Cycle



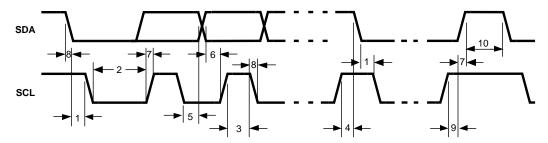


Figure 42. I²C Timing Diagram

FC Timing Parameters ($V_{DD1,2} = 3.0$ to 4.5V, $V_{DD IO} = 1.65$ V to $V_{DD1,2}$)

Cumbal	Dozemeter	Limi	Limit ⁽¹⁾		
Symbol	Parameter	Min	900 900 900 300 300	Unit	
1	Hold Time (repeated) START Condition	0.6		μs	
2	Clock Low Time	1.3		μs	
3	Clock High Time	600		ns	
4	Setup Time for a Repeated START Condition	600		ns	
5	Data Hold Time (Output direction, delay generated by LP3954)	300	900	ns	
5	Data Hold Time (Input direction, delay generated by the Master)	0	900	ns	
6	Data Setup Time	100		ns	
7	Rise Time of SDA and SCL	20+0.1C _b	300	ns	
8	Fall Time of SDA and SCL	15+0.1C _b	300	ns	
9	Set-up Time for STOP condition	600		ns	
10	Bus Free Time between a STOP and a START Condition	1.3		μs	
C _b	Capacitive Load for Each Bus Line	10	200	pF	

(1) NOTE: Data ensured by design

Autoincrement mode is available, with this possible read or write few byte with autoincreasing addresses, but LP3954 has holes in address register map, and is recommended to use autoincrement mode only for the pattern command registers.

Recommended External Components

OUTPUT CAPACITOR, COUT

The output capacitor C_{OUT} directly affects the magnitude of the output ripple voltage. In general, the higher the value of C_{OUT} , the lower the output ripple magnitude. Multilayer ceramic capacitors with low ESR are the best choice. At the lighter loads, the low ESR ceramics offer a much lower Vout ripple that the higher ESR tantalums of the same value. At the higher loads, the ceramics offer a slightly lower Vout ripple magnitude than the tantalums of the same value. However, the dv/dt of the Vout ripple with the ceramics is much lower that the tantalums under all load conditions. Capacitor voltage rating must be sufficient, 10V or greater is recommended.

Some ceramic capacitors, especially those in small packages, exhibit a strong capacitance reduction with the increased applied voltage. The capacitance value can fall to below half of the nominal capacitance. Too low output capacitance will increase the noise and it can make the boost converter unstable.

INPUT CAPACITOR, CIN

The input capacitor C_{IN} directly affects the magnitude of the input ripple voltage and to a lesser degree the V_{OUT} ripple. A higher value C_{IN} will give a lower V_{IN} ripple. Capacitor voltage rating must be sufficient, 10V or greater is recommended.

Product Folder Links: LP3954



OUTPUT DIODE, Dout

A Schottky diode should be used for the output diode. To maintain high efficiency the average current rating of the schottky diode should be larger than the peak inductor current (1A). Schottky diodes with a low forward drop and fast switching speeds are ideal for increasing efficiency in portable applications. Choose a reverse breakdown of the schottky diode larger than the output voltage. Do not use ordinary rectifier diodes, since slow switching speeds and long recovery times cause the efficiency and the load regulation to suffer.

INDUCTOR, L1

The LP3954's high switching frequency enables the use of the small surface mount inductor. A 4.7 μ H shielded inductor is suggested for 2 MHz operation, 10 μ H should be used at 1 MHz. The inductor should have a saturation current rating higher than the peak current it will experience during circuit operation (1A). Less than 300 m Ω ESR is suggested for high efficiency. Open core inductors cause flux linkage with circuit components and interfere with the normal operation of the circuit. This should be avoided. For high efficiency, choose an inductor with a high frequency core material such as ferrite to reduce the core losses. To minimize radiated noise, use a toroid, pot core or shielded core inductor. The inductor should be connected to the SW pin as close to the IC as possible.

LIST OF RECOMMENDED EXTERNAL COMPONENTS

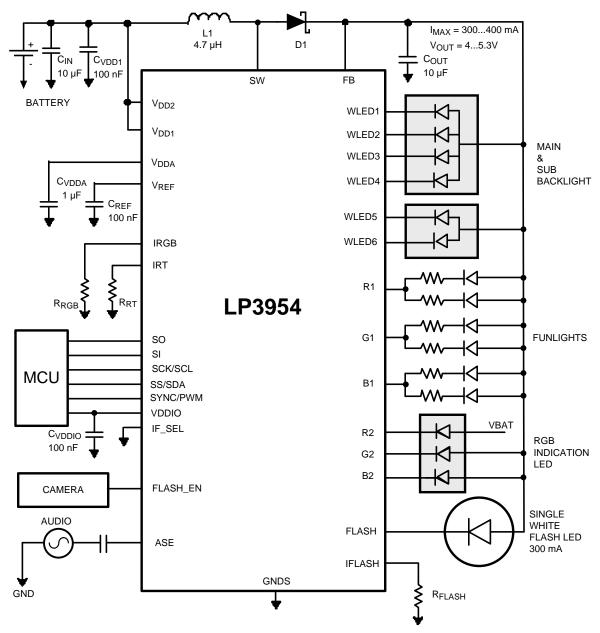
Symbol	Symbol Explanation	Value	Unit	Туре	
C _{VDD1}	C between VDD1 and GND	100	nF	Ceramic, X7R / X5R	
C _{VDD2}	C between VDD2 and GND	100	nF	Ceramic, X7R / X5R	
C_{VDDIO}	C between VDDIO and GND	100	nF	Ceramic, X7R / X5R	
C_{VDDA}	C between VDDA and GND	1	μF	Ceramic, X7R / X5R	
C _{OUT}	C between FB and GND	10	μF	Ceramic, X7R / X5R, 10V	
C _{IN}	C between battery voltage and GND	10	μF	Ceramic, X7R / X5R	
L _{BOOST}	L between SW and V _{BAT} at 2 MHz	4.7	μH	Shielded,low ESR, Isat 1A	
C _{VREF}	C between V _{REF} and GND	100	nF	Ceramic, X7R	
C _{VDDIO}	C between V _{DDIO} and GND	100	nF	Ceramic, X7R	
R _{FLASH}	R between I _{FLASH} and GND	1.2	kΩ	±1%	
R _{RBG}	R between I _{RGB} and GND	5.6	kΩ	±1%	
R _{RT}	R between I _{RT} and GND	82	kΩ	±1%	
D _{OUT}	Rectifying Diode (Vf at maxload)	0.3	V	Schottky diode	
C _{ASE}	C between Audio input and ASE	100	nF	Ceramic, X7R / X5R	
LEDs			User defined		
D _{LIGHT}	Light Sensor		TDK	BSC2015	

Submit Documentation Feedback
Product Folder Links: LP3954



Application Examples

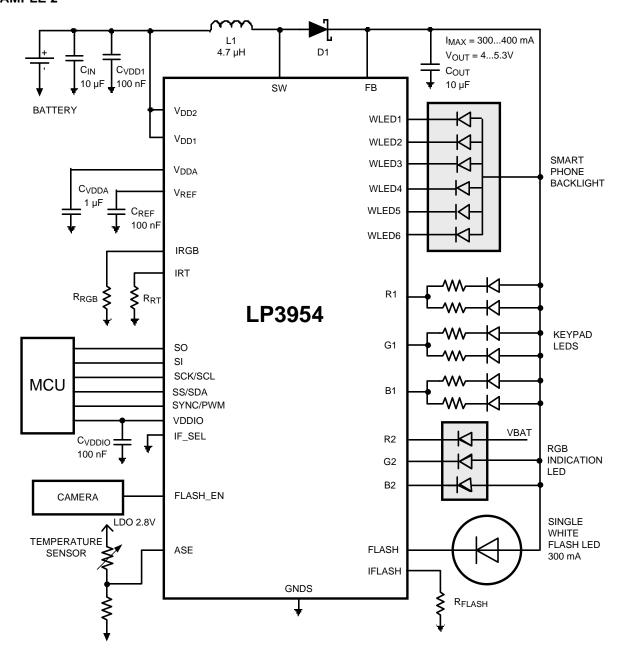
EXAMPLE 1



- MAIN BACKLIGHT
- SUB BACKLIGHT
- AUDIO SYNCHRONIZED FUNLIGHTS
- RGB INDICATION LIGHT
- FLASH LED

Figure 43. Flip Phone



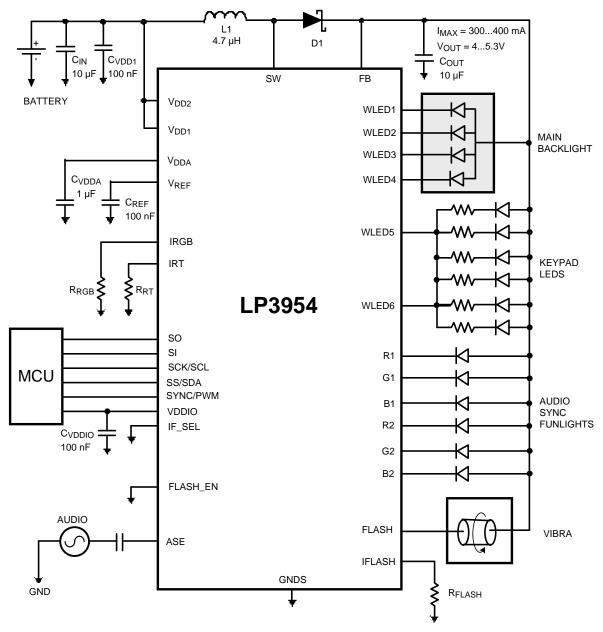


- 6 WHITE LED BACKLIGHT
- **KEY PAD LIGHTS**
- **RGB INDICATION LED**
- WHITE SINGLE LED FLASH
- TEMPERATURE SENSOR

Figure 44. Smart Phone

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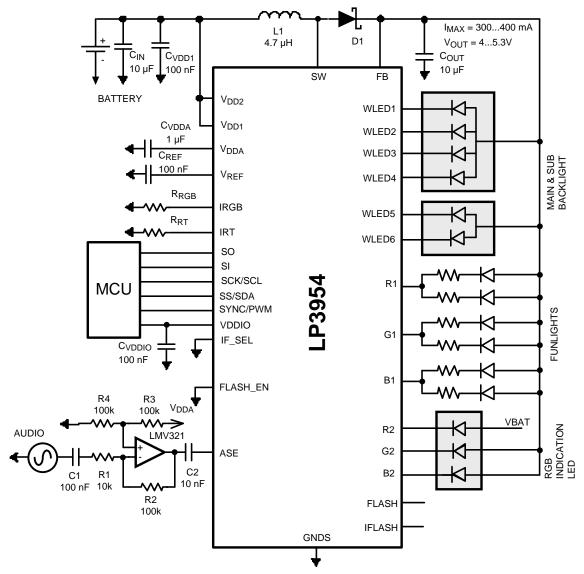




- MAIN BACKLIGHT
- KEYPAD LIGHTS
- AUDIO SYNCHRONIZED FUNLIGHTS
- VIBRA

Figure 45. Candybar Phone



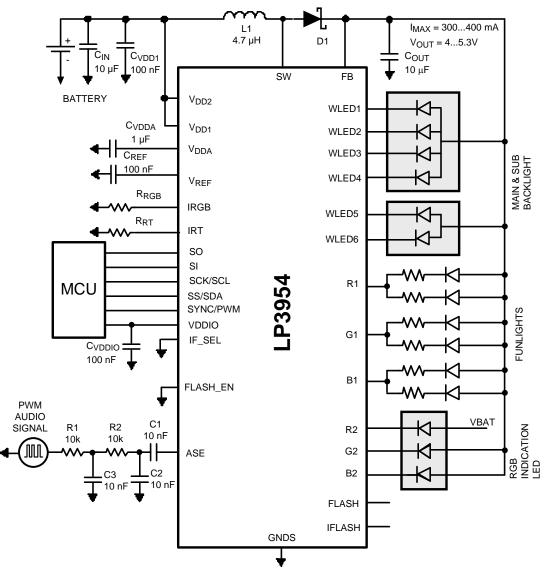


- MAIN BACKLIGHT
- SUB BACKLIGHT
- AUDIO SYNCHRONIZED FUNLIGHTS
- RGB INDICATION LIGHT

There may be cases where the audio input signal going into the LP3954 is too weak for audio synchronization. This figure presents a single-supply inverting amplifier connected to the ASE input for audio signal amplification. The amplification is +20 dB, which is well enough for 20 mVp-p audio signal. Because the amplifier (LMV321) is operating in single supply voltage, a voltage divider using R3 and R4 is implemented to bias the amplifier so the input signal is within the input common-mode voltage range of the amplifier. The capacitor C1 is placed between the inverting input and resistor R1 to block the DC signal going into the audio signal source. The values of R1 and C1 affect the cutoff frequency, fc = 1/(2*Pi*R1*C1), in this case it is around 160 Hz. As a result, the LMV321 output signal is centered around mid-supply, that is $V_{DDA}/2$. The output can swing to both rails, maximizing the signal-to-noise ratio in a low voltage system

Figure 46. Using Extra Amplifier





- MAIN BACKLIGHT
- SUB BACKLIGHT
- AUDIO SYNCHRONIZED FUNLIGHTS
- RGB INDICATION LIGHT

Here, a second order RC-filter is used on the ASE input to convert a PWM signal to an analog waveform.

Figure 47. Using PWM Signal

More application information is available in the document "LP3954 Evaluation Kit".



LP3954 Control Registers

Table 3. LP3954 Control Register Names and Default Values

RGB Ctrl Ext. PWM control	cc_rgb1	cc_rgb2	r1sw	g1sw	b1sw	r2sw	a2011	L.O
Ext. PWM control	1			9	51011	12300	g2sw	b2sw
Ext. PWM control		1	0	0	0	0	0	0
	wled1_4 _pwm	wled5_6 _pwm	r1_pwm	g1_pwm	b1_pwm	r2_pwm	g2_pwm	b2_pwm
	0	0	0	0	0	0	0	0
WLED control			slope	fade_sel	en_fade	displ	en_w1_4	en_w5_6
			0	0	0	0	0	0
WLED1-4				wled1	_4[7:0]			
	0	0	0	0	0	0	0	0
WLED5-6				wled5	_6[7:0]			
	0	0	0	0	0	0	0	0
Enables	pwm_ sync	nstby	en_ boost			en_ autoload	rgb_s	el[1:0]
	0	0	0			1	0	0
ADC output		1		data	a[7:0]	I		
	0	0	0	0	0	0	0	0
Boost output		1		boos	st[7:0]	I		
	0	0	1	1	1	1	1	1
Boost_frq							1	
				1		1	1	1
HC_Flash			hc_pwm	fl_t	[1:0]	hc[1:0]	en_ hcflash
			0	0	0	0	0	0
Pattern gen ctrl						rgb_start	loop	log
					1	0	0	0
RGB1 max current				_				[1:0]
	_		-		-	-		0
RGB2 max current				_				[1:0]
	_		0					0
audio sync CTRL1		1		-			-	
	0	0	0					1
audio sync CTRL2							1	
		[0.0]		U		U		0
Command 1A								
0			U	·	U	U	1	0
Command 1B						•		
Command 2A	- 0		U	U		U		0
Command 2A					I	•		
O			U	1	U	U	1	0
Command 2B				1		•	1	
Command 2A	- 0		U	U		U		0
Command 3A			•	^	1	^		1
Commercial 2D			U	-	U	U		0
Commana 3B			•	1		•	1	_
Commercial 44	U		U	U		U		0
Command 4A	_		•	_	1	•		
	0	0 [1:0]	0	0	0	0	0 tt[2:0]	0
Command 4B				b[2:0]				
	WLED5-6 Enables ADC output Boost output Boost_frq HC_Flash Pattern gen ctrl	O O O O O O O O O O	O O O	WLED1-4	WLED1-4	WLED1-4	WLED1-4	WLED5-6



Table 3. LP3954 Control Register Names and Default Values (continued)

ADDR (HEX)	REGISTER	D7	D6	D5	D4	D3	D2	D1	D0
58	Command 5A		r[2:0]			g[2:0]		cet	[3:2]
		0	0	0	0	0	0	0	0
59	Command 5B	cet	[1:0]		b[2:0]			tt[2:0]	
		0	0	0	0	0	0	0	0
5A	Command 6A		r[2:0]			g[2:0]		cet	[3:2]
		0	0	0	0	0	0	0	0
5B	Command 6B	cet[1:0]			b[2:0]			tt[2:0]	
		0	0	0	0	0	0	0	0
5C	Command 7A	r[2:0]			g[2:0]			cet[3:2]	
		0	0	0	0	0	0	0	0
5D	Command 7B	cet	[1:0]		b[2:0]			tt[2:0]	
		0	0	0	0	0	0	0	0
5E	Command 8A		r[2:0]		g[2:0]			cet[3:2]	
		0	0	0	0	0	0	0	0
5F Cor	Command 8B	cet	[1:0]		b[2:0]	•		tt[2:0]	•
		0	0	0	0	0	0	0	0
60	Reset	Writing any data to Reset Register resets LP3954							

LP3954 Registers

REGISTER BIT EXPLANATIONS

Each register is shown with a key indicating the accessibility of the each individual bit, and the initial condition:

Register Bit Accessibility and Initial Condition					
Key	Bit Accessibility				
rw	Read/write				
r	Read only				
-0,-1	Condition after POR				

RGB CTRL (00H) - RGB LEDS CONTROL REGISTER

D7	D6	D5	D4	D3	D2	D1	D0
cc_rgb1	cc_rgb2	r1sw	g1sw	b1sw	r2sw	g2sw	b2sw
rw-1	rw-1	rw-0	rw-0	rw-0	rw-0	rw-0	rw-0

cc_rgb1	Bit 7	0 - R1, G1 and B1 are constant current sinks, current limited internally 1 - R1, G1 and B1 are switches, limit current with external ballast resistor
cc_rgb2	Bit 6	0 – R2, G2 and B2 are constant current sinks, current limited internally 1 – R2, G2 and B2 are switches, limit current with external ballast resistor
r1sw	Bit 5	0 – R1 disabled 1 – R1 enabled
g1sw	Bit 4	0 – G1 disabled 1 – G1 enabled
b1sw	Bit 3	0 – B1 disabled 1 – B1 enabled
r2sw	Bit 2	0 – R2 disabled 1 – R2 enabled
g2sw	Bit 1	0 – G2 disabled 1 – G2 enabled
b2sw	Bit 0	0 – B2 disabled 1 – B2 enabled



EXT_PWM_CONTROL (07H) - EXTERNAL PWM CONTROL REGISTER

D7	D6	D5	D4	D3	D2	D1	D0
wled1_4_pwm	wled5_6_pwm	r1_pwm	g1_pwm	b1_pwm	r2_pwm	g2_pwm	b2_pwm
rw-0	rw-0	rw-0	rw-0	rw-0	rw-0	rw-0	rw-0

wled1_4_pwm	Bit 7	0 – WLED1WLED4 PWM control disabled 1 – WLED1WLED4 PWM control enabled
wled5_6_pwm	Bit 6	0 – WLED5, WLED6 PWM control disabled 1 – WLED5, WLED6 PWM control enabled
r1_pwm	Bit 5	0 – R1 PWM control disabled 1 – R1 PWM control enabled
g1_pwm	Bit 4	0 – G1 PWM control disabled 1 – G1 PWM control enabled
b1_pwm	Bit 3	0 – RB PWM control disabled 1 – B1 PWM control enabled
r2_pwm	Bit 2	0 – R2 PWM control disabled 1 – R2 PWM control enabled
g2_pwm	Bit 1	0 – G2 PWM control disabled 1 – G2 PWM control enabled
b2_pwm	Bit 0	0 – B2 PWM control disabled 1 – B2 PWM control enabled

WLED CONTROL (08H) - WLED CONTROL REGISTER

D7	D6	D5	D4	D3	D2	D1	D0
		slope	fade_sel	en_fade	displ	en_w1_4	en_w5_6
r-0	r-0	rw-0	rw-0	rw-0	rw-0	rw-0	rw-0

slope	Bit 5	0 – fade execution time 1.3 sec 1 – fade execution time 0.65 sec
fade_sel	Bit 4	0 – fade control for WLED1 WLED4 1 – fade control for WLED5, WLED6
en_fade	Bit 3	0 – automatic fade disabled 1 – automatic fade enabled
displ	Bit 2	0 – WLED1-4 and WLED5-6 are controlled separately 1 – WLED1-4 and WLED5-6 are controlled with WLED1-4 controls
en_w1_4	Bit 1	0 – WLED1WLED4 disabled 1 – WLED1WLED4 enabled
en_w5_6	Bit 0	0 – WLED5,WLED6 disabled 1 – WLED5,WLED6 enabled

WLED1-4 (09H) – WLED1...WLED4 BRIGHTNESS CONTROL REGISTER

D7	D6	D5	D4	D3	D2	D1	D0			
	wled1_4[7:0]									
rw-0	rw-0	rw-0	rw-0	rw-0	rw-0	rw-0	rw-0			



		Adjustment				
		wled1_4[7:0]	Typical driver current (ma)			
		0000 0000	0			
		0000 0001	0.1			
		0000 0010	0.2			
wled1_4[7:0]	Bits 7-0	0000 0011	0.3			
		0000 0100	0.4			
		1111 1101	25.3			
		1111 1110	25.4			
		1111 1111	25.5			

WLED5-6 (0AH) - WLED5, WLED6 BRIGHTNESS CONTROL REGISTER

D7	D6	D5	D4	D3	D2	D1	D0
	wled5_5[7:0]						
rw-0	rw-0	rw-0	rw-0	rw-0	rw-0	rw-0	rw-0

		Adjustment				
		wled5_6[7:0]	Typical driver current (ma)			
		0000 0000	0			
		0000 0001	0.1			
		0000 0010	0.2			
wled5_6[7:0]	Bits 7-0	0000 0011	0.3			
		0000 0100	0.4			
		1111 1101	25.3			
		1111 1110	25.4			
		1111 1111	25.5			

ENABLES (0BH) – ENABLES REGISTER

D7	D6	D5	D4	D3	D2	D1	D0
pwm_sync	nstby	en_boost			en_autoload	rgb_s	el[1:0]
rw-0	rw-0	rw-0	r-0	r-0	rw-1	rw-0	rw-0

pwm_sync	Bit 7	0 – synchronization to external clock disabled 1 – synchronization to external clock enabled				
nstby	Bit 6	0 – LP3954 standby mode 1 – LP3954 active mode				
en_boost	Bit 5	0 – boost converter disabled 1 – boost converter enabled				
en_autoload	Bit 2	0 – internal boost converter active load off 1 – internal boost converter active load on				
		Color LED control mode selection				
		rgb_sel[1:0]	Audio sync connected to	Pattern generator connected to		
rgb_sel[1:0]	Bits 1-0	00	none	RGB1 & RGB2		
		01	RGB1	RGB2		
		10	RGB2	RGB1		
		11	RGB1 & RGB2	none		



ADC_OUTPUT (0CH) - ADC DATA REGISTER

D7	D6	D5	D4	D3	D2	D1	D0	
	data[7:0]							
r-0								

data[7:0]	Bits 7-0	Data register ADC (Audio input, light or temperature sensors)
-----------	----------	---

BOOST_OUTPUT (0DH) - BOOST OUTPUT VOLTAGE CONTROL REGISTER

D7	D6	D5	D4	D3	D2	D1	D0
	Boost[7:0]						
rw-0							

			Adjustment
		Boost[7:0]	Typical boost output (V)
		0000 0000	4.00
		0000 0001	4.25
		0000 0011	4.40
Boost[7:0]	Bits 7-0	0000 0111	4.55
		0000 1111	4.70
		0001 1111	4.85
		0011 1111	5.00 (default)
		0111 1111	5.15
		1111 1111	5.30

BOOST_FRQ (0EH) - BOOST FREQUENCY CONTROL REGISTER

D7	D6	D5	D4	D3	D2	D1	D0
						freq_sel[2:0]	
r-0	r-0	r-0	r-0	r-0	rw-1	rw-1	rw-1

		A	djustment
		freq_sel[2:0]	Frequency
freq_sel[2:0]	Bits 7-0	1xx	2.00 MHz
		01x	1.67 MHz
		00x	1.00 MHz

HC_FLASH (10H) - HIGH CURRENT FLASH DRIVER CONTROL REGISTER

D7	D6	D5	D4	D3	D2	D1	D0
		hc_pwm	fl_t[1:0]		hc[1:0]		en_hcflash
r-0	r-0	rw-0	rw-0	rw-0	rw-0	rw-0	rw-0

hc_pwm	Bit 5	0 – PWM for high current flash driver disabled1 – PWM for high current flash driver enabled		
			Flash duration for high current driver	
		fl_t[1:0]	Typical flash duration	
fl_t[1:0]	Bits 4-3	00	200 ms	
11_1[1.0]	DIIS 4-3	01	400 ms	
		10	600 ms	
		11	According EN_FLASH pin on duration	



hald 01		Current control for high current flash driver				
		hc[1:0]	current			
	Bits 2-1	00	0.25×I _{MAX(FLASH)}			
hc[1:0]	DIIS 2-1	01	0.50×I _{MAX(FLASH)}			
		10	0.75×I _{MAX(FLASH)}			
		11	1.00×I _{MAX(FLASH)}			
en_hcflash	Bit 0	0 – high current flas 1 – high current flas				

PATTERN_GEN_CTRL (11H) - PATTERN GENERATOR CONTROL REGISTER

D7	D6	D5	D4	D3	D2	D1	D0
						loop	log
r-0	r-0	r-0	r-0	r-0	rw-0	rw-0	rw-0

rgb_start	Bit 2	0 – Pattern generator disabled 1 – execution pattern starting from command 1
Іоор	Bit 1	0 – pattern generator loop disabled (single patter) 1 – pattern generator loop enabled (execute until stopped)
log	Bit 0	0 – color intensity mode 0 1 – color intensity mode 1

RGB1_MAX_CURRENT (12H) - RGB1 DRIVER INDIVIDUAL MAXIMUM CURRENT CONTROL REGISTER

D7	D6	D5	D4	D3	D2	D1	D0
	ir1[1:0]		ig1[1:0]		ib1[1:0]		
r-0	r-0	rw-0	rw-0	rw-0	rw-0	rw-0	rw-0

		Max	kimum current for R1 driver
		ir1[2:0]	Maximum output current
ir1[1:0]	Bits 5-4	00	0.25×I _{MAX}
11 1[1.0]	DIIS 5-4	01	0.50×I _{MAX}
		10	0.75×I _{MAX}
		11	1.00×I _{MAX}
		1ax	timum current for G1 driver
	01 Bits 3-2	ig2[1:0]	Maximum output current
ia1[1:0]		00	0.25×I _{MAX}
ig1[1:0]	DIIS 3-2	01	0.50×I _{MAX}
		10	0.75×I _{MAX}
		11	1.00×I _{MAX}
		Max	ximum current for B1 driver
		ib1[1:0]	Maximum output current
ib4[4.0]	Bits 1-0	00	0.25×I _{MAX}
ib1[1:0]	DIIS 1-0	01	0.50×I _{MAX}
		10	0.75×I _{MAX}
		11	1.00×I _{MAX}

RGB2_MAX_CURRENT (13H) - RGB2 DRIVER INDIVIDUAL MAXIMUM CURRENT CONTROL REGISTER

D7	D6	D5	D4	D3	D2	D1	D0
ir2[1:0]		[1:0]	ig2	[1:0]	ib2[[1:0]	
rw-0	rw-0	rw-0	rw-0	rw-0	rw-0	rw-0	rw-0



		Max	ximum current for R2 driver	
		ir2[2:0]	Maximum output current	
:-0[4-0]	D:4- 5 4	00	0.25×I _{MAX}	
ir2[1:0]	Bits 5-4	01	0.50×I _{MAX}	
		10	0.75×I _{MAX}	
		11	1.00×I _{MAX}	
		Max	ximum current for G2 driver	
	Bits 3-2	ig2[1:0]	Maximum output current	
in 2[4,0]		Dito 2 2	00	0.25×I _{MAX}
ig2[1:0]		01	0.50×I _{MAX}	
		10	0.75×I _{MAX}	
		11	1.00×I _{MAX}	
		Max	ximum current for B2 driver	
		ib2[1:0]	Maximum output current	
:h2[4.0]	Bits 1-0	00	0.25×I _{MAX}	
ib2[1:0]	DII2 1-0	01	0.50×I _{MAX}	
		10	0.75×I _{MAX}	
1		11	1.00×I _{MAX}	

AUDIO_SYNC_CTRL1 (2AH) - AUDIO SYNCHRONIZATION AND ADC CONTROL REGISTER 1

D7	D6	D5	D4	D3	D2	D1	D0
	gain_sel[2:0]			en_agc	en_sync	input_s	sel[1:0]
rw-0	rw-0	rw-0	rw-0	rw-0	rw-0	rw-1	rw-1

			Input signal gain control
		gain_sel[2:0]	gain, db
		000	0 (default)
		001	3
main call2:01	Bits 7-5	010	6
gain_sel[2:0]	DIIS 7-5	011	9
		100	12
		101	15
		110	18
		111	21
sync_mode	Bit 4	Input filter mode control 0 – Amplitude mode 1 – Frequency mode	
en_agc	Bit 3	0 – automatic gain control of 1 – automatic gain control e	disabled enabled
en_sync	Bit 2	0 – audio synchronization d 1 – audio synchronization e	
			ADC input selector
		input_sel[1:0]	Input
input col[1:0]	Bits 1-0	00	Single ended input signal (ASE)
input_sel[1:0]	DIIS 1-0	01	Temperature measurement
		10	Ambient light measurement
		11	No input (default)



AUDIO_SYNC_CTRL2 (2BH) - AUDIO SYNCHRONIZATION AND ADC CONTROL REGISTER 2

D7	D6	D5	D4	D3	D2	D1	D0
		en_avg	mode_	ctrl[1:0]	speed_	ctrl[1:0]	
r-0	r-0	r-0	rw-0	rw-0	rw-0	rw-0	rw-0

en_avg	Bit 4	0 – averaging disabled 1 – averaging enabled				
mode_ctrl[1:0]	Bits 3-2	Filtering mode control				
		LEDs light response time to audio input				
		speed_ctrl[1:0]	Response			
anand atriff1:01	Bits 1-0	00	FASTEST (default)			
speed_ctrl[1:0]	Bits 1-0	01	FAST			
		10	MEDIUM			
		11	SLOW			

PATTERN CONTROL REGISTERS

Command_[1:8]A – Pattern Control Register A									
D7	D6	D5	D4	D3	D2	D1	D0		
r[2:0]				g[2:0]		cet[3:2]		
rw-0	rw-0	rw-0	rw-0	rw-0	rw-0	rw-0	rw-0		

Command_[1:8]B - Pattern Control Register B											
D7 D6 D5 D4 D3 D2 D1 D0											
cet	1:0]		b[2:0]								
rw-0	rw-0	rw-0	rw-0	rw-0	rw-0	rw-0	rw-0				

			Red color intensity					
		r[2:0]	current, %					
			log=0	log=1				
		000	0×I _{MAX}	0×I _{MAX}				
	001	7%×I _{MAX}	1%×I _{MAX}					
*[2.0]	Bits	010	14%×I _{MAX}	2%×I _{MAX}				
r[2:0]	7-5A	011	21%×I _{MAX}	4%×I _{MAX}				
		100	32%×I _{MAX}	10%×I _{MAX}				
		101	46%×I _{MAX}	21%×I _{MAX}				
		110	71%×I _{MAX}	46%×I _{MAX}				
		111	100%×I _{MAX}	100%×I _{MAX}				
		* log bit is in pattern_gen_c	ctrl register					





			Green color intensity	
		g[2:0]	curre	ent, %
			log=0	log=1
		000	0×I _{MAX}	0×I _{MAX}
	Rite	001	7%×I _{MAX}	1%×I _{MAX}
~[0.0]	Bits	010	14%×I _{MAX}	2%×I _{MAX}
g[2:0]	4-2A	011	21%×I _{MAX}	4%×I _{MAX}
		100	32%×I _{MAX}	10%×I _{MAX}
		101	46%×I _{MAX}	21%×I _{MAX}
		110	71%×I _{MAX}	46%×I _{MAX}
		111	100%×I _{MAX}	100%×I _{MAX}
		* log bit is in pattern_gen_ctr	l register	
		Command	d execution time	
		cet[3:0]	CET duration, ms	
		0000	197	
		0001	393	
		0010	590	
		0011	786	
		0100	983	
		0101	1180	
0.04[2:0]	Bits	0110	1376	
cet[3:0]	1-0A 7-6B	0111	1573	
		1000	1769	
		1001	1966	
		1010	2163	
		1011	2359	
		1100	2556	
		1101	2753	
		1110	2949	
		1111	3146	
			Blue color intensity	
		b[2:0]	curre	ent, %
			log=0	log=1
		000	0×I _{MAX}	0×I _{MAX}
		001	7%×I _{MAX}	1%×I _{MAX}
b[2:0]	Bits	010	14%×I _{MAX}	2%×I _{MAX}
D[2.0]	5-3B	011	21%×I _{MAX}	4%×I _{MAX}
		100	32%×I _{MAX}	10%×I _{MAX}
		101	46%×I _{MAX}	21%×I _{MAX}
		110	71%×I _{MAX}	46%×I _{MAX}
		111	100%×I _{MAX}	100%×I _{MAX}
		* log bit is in pattern_gen_ctr	l register	

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			Transition time
		tt[2:0]	Transition time, ms
		000	0
	Bits 2-0B	001	55
10.01		010	110
tt[2:0]		011	221
		100	442
		101	885
		110	1770
		111	3539

RESET (60H) - RESET REGISTER

D7	D1	D0										
	Writing any data to Reset Register in address 60H can reset LP3954											
r-0 r-0 r-0 r-0 r-0 r-0												





REVISION HISTORY

Cł	hanges from Revision C (March 2013) to Revision D	Page
•	Changed layout of National Data Sheet to TI format	52



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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LP3954TL/NOPB	ACTIVE	DSBGA	YZR	36	250	RoHS & Green	SNAGCU	Level-1-260C-UNLIM	-30 to 85	D49B	Samples
LP3954TLX/NOPB	ACTIVE	DSBGA	YZR	36	1000	RoHS & Green	SNAGCU	Level-1-260C-UNLIM	-30 to 85	D49B	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LP3954TL/NOPB	DSBGA	YZR	36	250	178.0	12.4	3.21	3.21	0.76	8.0	12.0	Q1
LP3954TLX/NOPB	DSBGA	YZR	36	1000	178.0	12.4	3.21	3.21	0.76	8.0	12.0	Q1

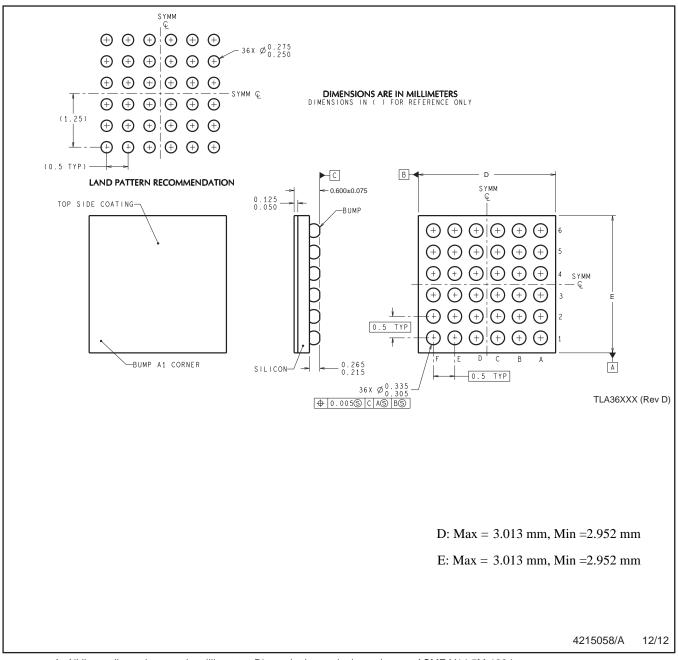


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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LP3954TL/NOPB	DSBGA	YZR	36	250	208.0	191.0	35.0
LP3954TLX/NOPB	DSBGA	YZR	36	1000	208.0	191.0	35.0



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994. B. This drawing is subject to change without notice.



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